

Fourth Quarter FY 2026
Quarterly Update

Infineon Technologies AG
Investor Relations

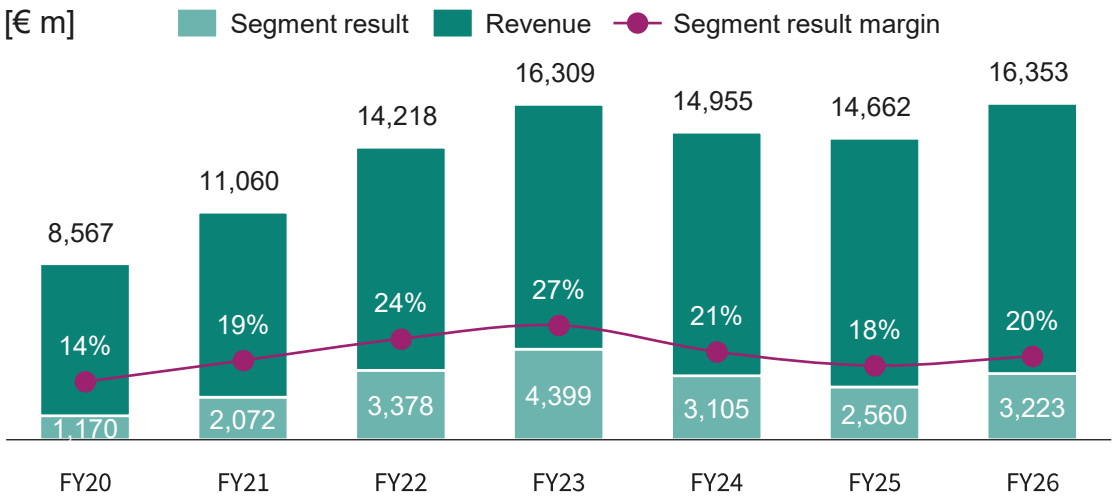
Public

Infineon at a glance

Infineon is a global semiconductor leader

Automotive	Power	Microcontroller
#1	#1	#1
TechInsights, April 2026	Omdia, May 2026	Omdia, May 2026

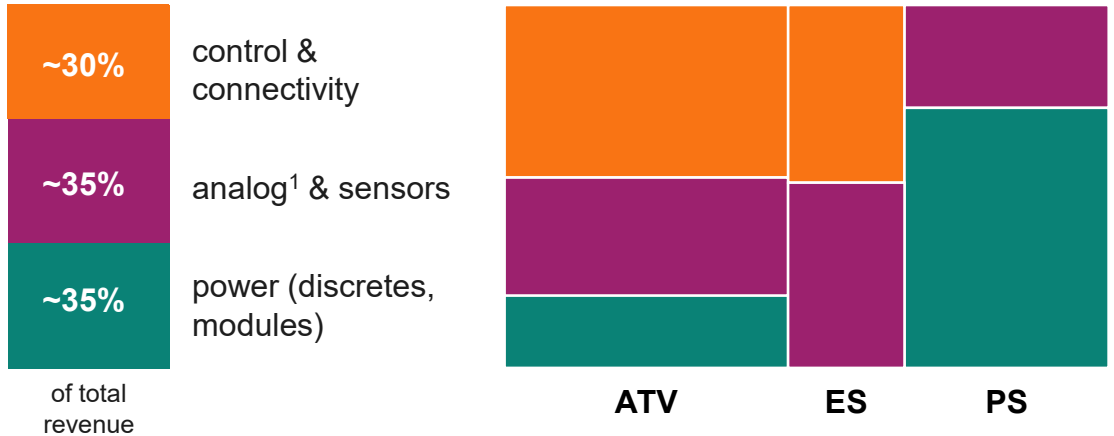
Financials



FY26 revenue by segment



FY26 revenue by product category



[1] including <5% of differentiating memory technologies

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New organizational structure geared toward bringing innovation to customers faster

Automotive (ATV)



Shaping the future of mobility
by making vehicles clean, safe, and smart.

Key applications	Software-defined vehicle E-mobility
Revenue share FY26	**48%**

Edge Systems (ES)



Advancing everyday life by enabling smart, seamless, and trusted human-technology interactions.

Key applications	Robotics and edge AI Smart living
Revenue share FY26	**19%**

Power Systems (PS)



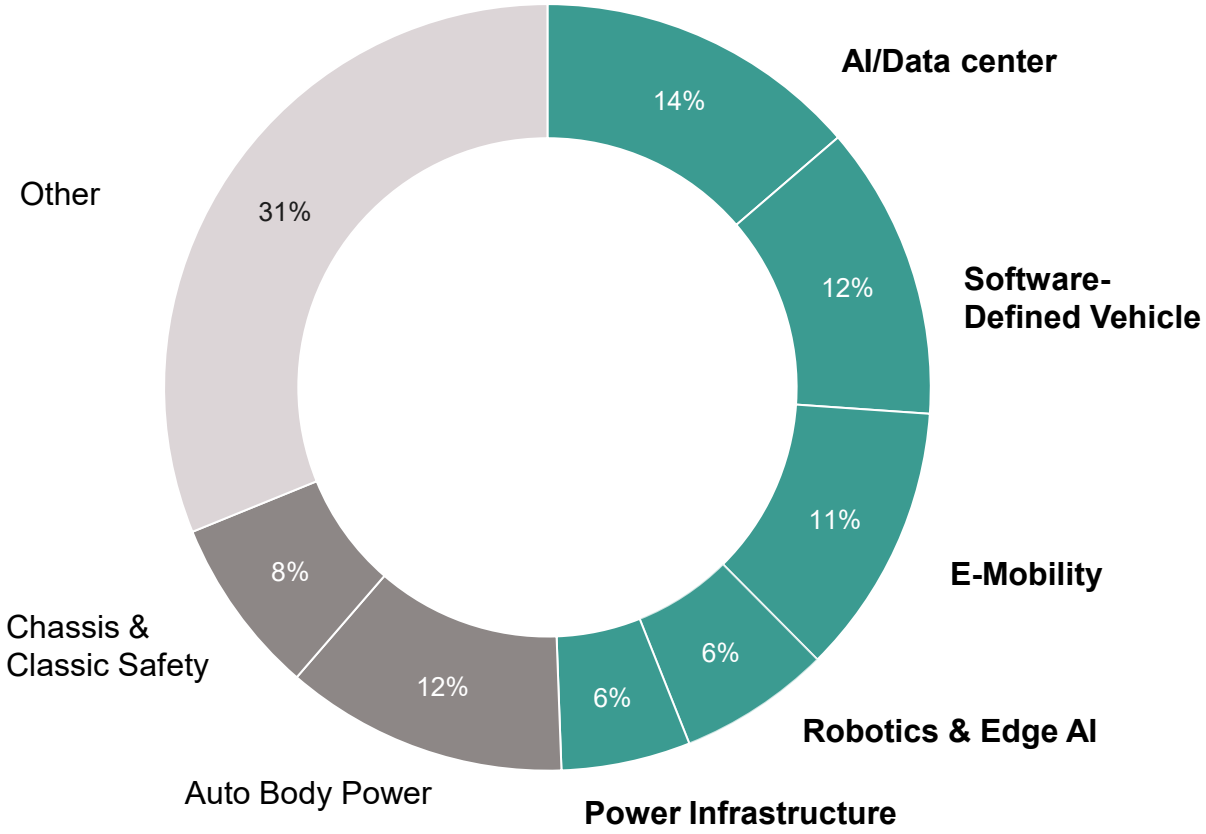
Powering the electrified world by enabling energy to flow efficiently, reliably, and at scale.

Key applications	Power infrastructure AI/data center
Revenue share FY26	**33%**

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Well-balanced portfolio and strong focus on key growth applications – they account for ~50% of revenue

FY26 revenue of €16,353m by key growth application



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Our Target Operating Model: committing to ambitious financial goals and being the sustainability leader

Target Operating Model
through cycle

Revenue growth	**>10%**
Segment Result Margin	**25%**
Adj. Free Cash Flow Margin[1]	**10-15%**

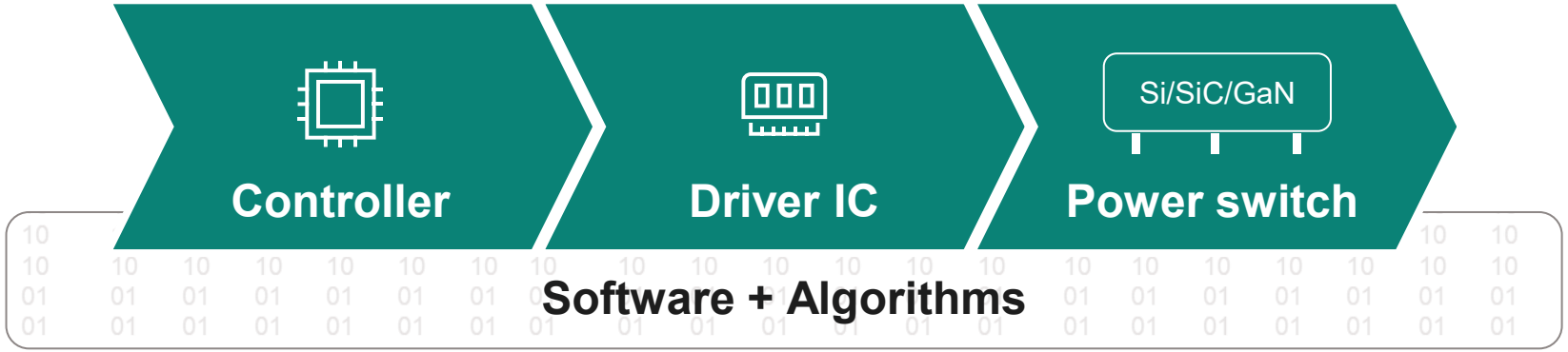
Sustainability leader
CO_2 neutrality 2030



[1] See notes for definition

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Undisputed power systems leadership mastering all three key materials



Leadership in power systems across all materials and technologies

Silicon
Diode – MOSFET – IGBT – Driver – Controller

Si



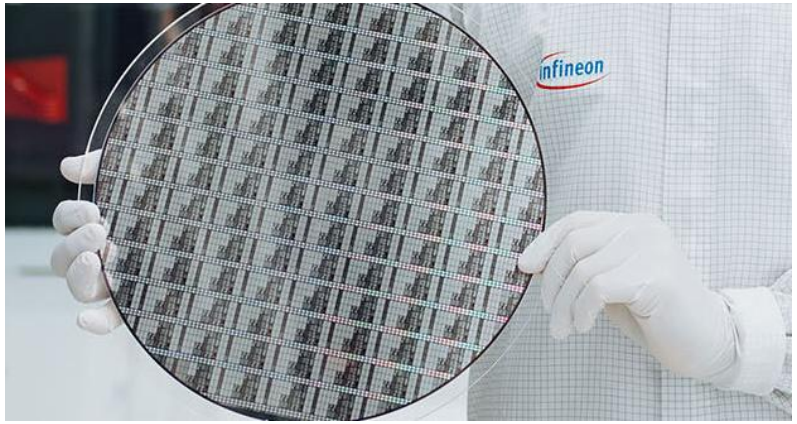
Silicon carbide
Diode – MOSFET

SiC



Gallium nitride
HEMT – Driver

GaN



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Continuous innovation establishes Infineon as the clear leader across all power semiconductor technologies



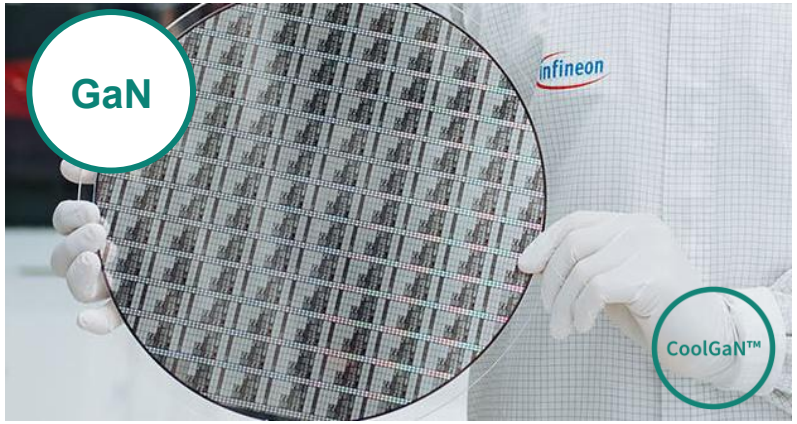
World's thinnest silicon power wafer with 20 µm on 300 mm

- Broadest Si-power **portfolio**
- Unmatched **quality** and leading in all figures of merit (FOM)
- Rising share of large **scale**, highly automated 300 mm manufacturing



World's most competitive 200 mm silicon carbide power fab

- Leading **trench** performance
- High reliability and robustness in extreme conditions
- **High scale & best cost** manufacturing
- Industry-**first** functional power devices processed on **300 mm** wafers



World's first 300 mm gallium nitride power wafer

- Highest **efficiency** at highest frequency → smallest system size
- Allows functional **integration**
- Enabling cost parity with silicon
- First **GaN 300 mm fab** with commercial scale starting 2027

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Whatever we do, wherever we are, digital technology is always present – AI as key catalyst for edge systems

Living





Working

Edge AI

Edge systems ensure that interaction between humans and the digital world works seamlessly

Sense

Compute

Connect

Secure

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Infineon manufacturing strategy balances differentiated inhouse manufacturing and outsourcing

Strategic differentiation through right mix of in-house manufacturing …

We manufacture **differentiating power & analog mixed-signal** primarily **in-house**

This results in a **differentiation potential** – technology, manufacturing processes, cost

IFX outsourcing share



… and outsourcing to strategic manufacturing partners

- Differentiation arises not from technology, but mainly from **product design** and **software**
- **Capital efficient** growth, flexibility and reduced risks
- **Strategic localization**

	IFX revenue split[1]	Foundry supply globally	IFX outsourcing share
Control & connectivity	~35%	High	High
Analog & sensors	~30%	Medium	Medium
Power	~35%	Low	Low

[1] Based on FY25 revenue

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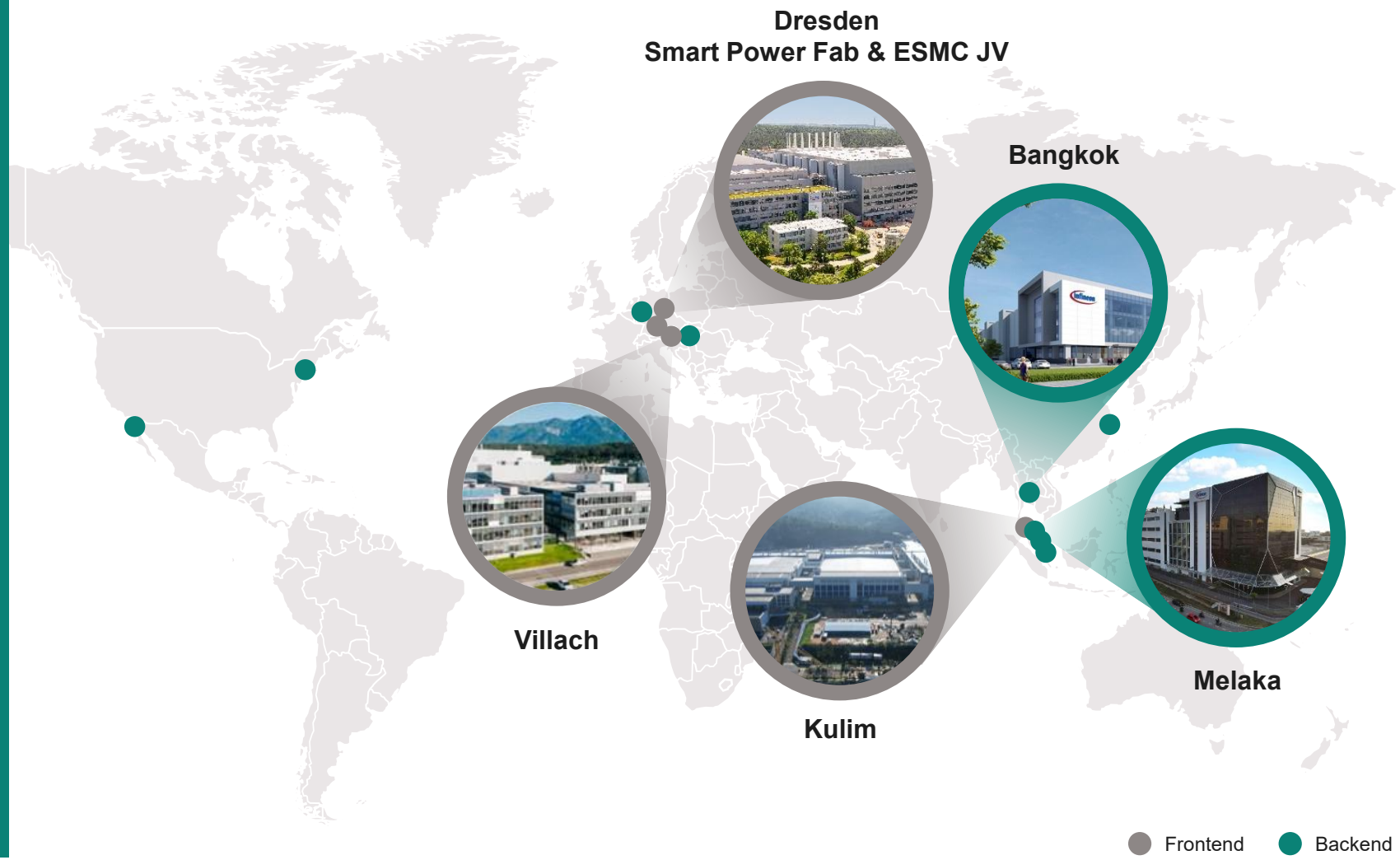
Our inhouse manufacturing footprint is streamlined, highly focused on scale, enabling cost competitiveness and growth

13 manufacturing sites + strong partner network
Optimized from 20 sites previously

Majority in 300 mm and best cost country
Further growing

Innovative packaging
is a key differentiator in Powering AI business

Enabling growth in existing clean room space



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In FY2026 Infineon exceeded its climate targets and is perceived in the market as a role model in terms of sustainability

FY26

100%
green electricity

PCF[1] for 50%
of the product portfolio

-81%
emissions compared to 2019 baseline



81%
waste recycling rate

2025
SBT-target validated

31%
water recycling rate

1:45
net ecological benefit

External recognitions of our performance

Ecovadis Platinum Award

In April 2026, Infineon received an MSCI ESG rating of AA.[2]

Listed in Dow Jones World Sustainability Index

B Climate Change and Water Security, CDP

Prime Status ISS ESG Corporate Rating

Industry Top Performer

[1] Product Carbon Footprint. | [2] MSCI Disclaimer

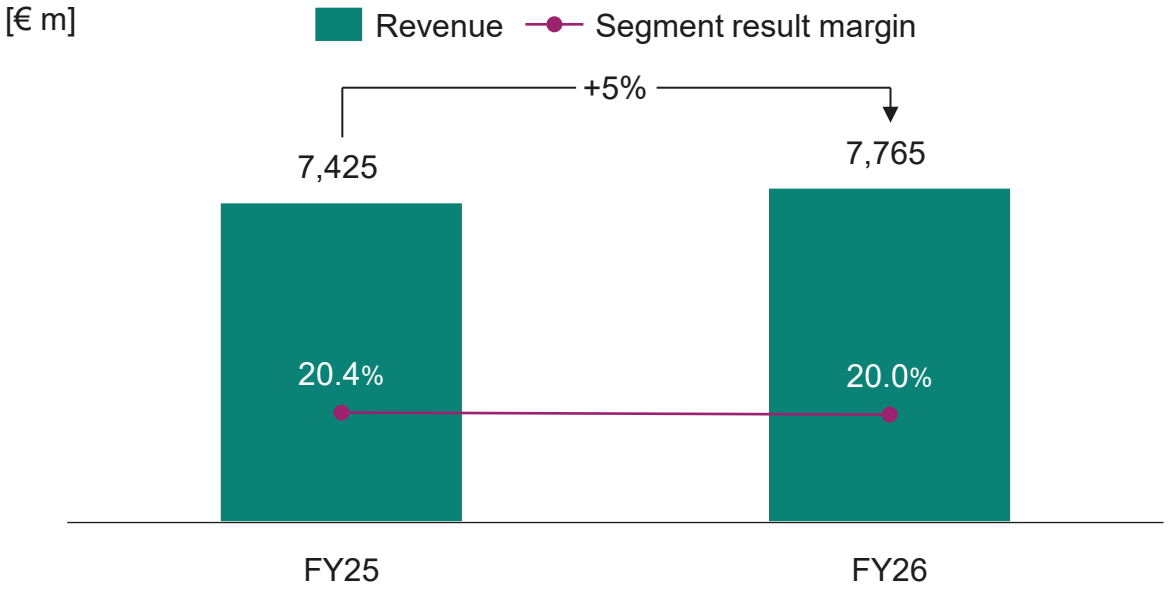
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Automotive

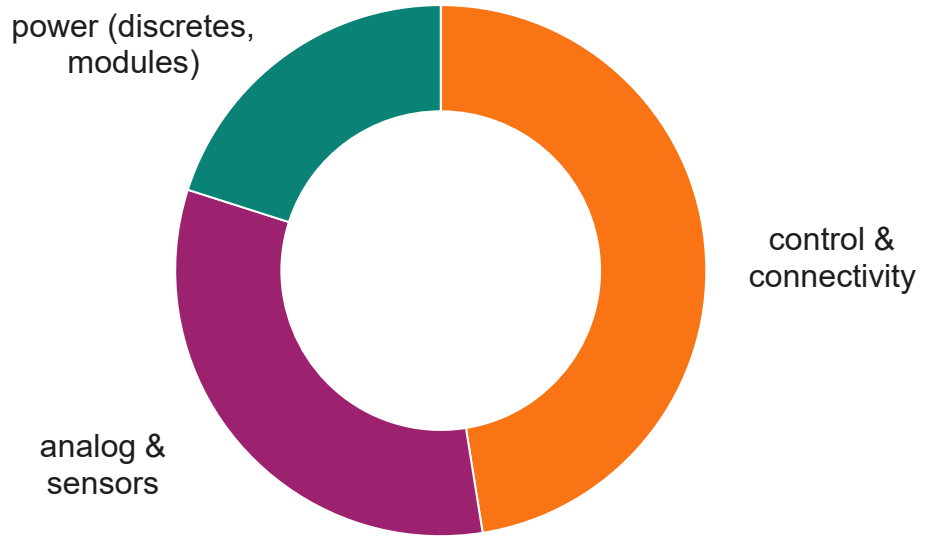


ATV at a glance

ATV revenue and segment result margin



FY26 revenue split by product group



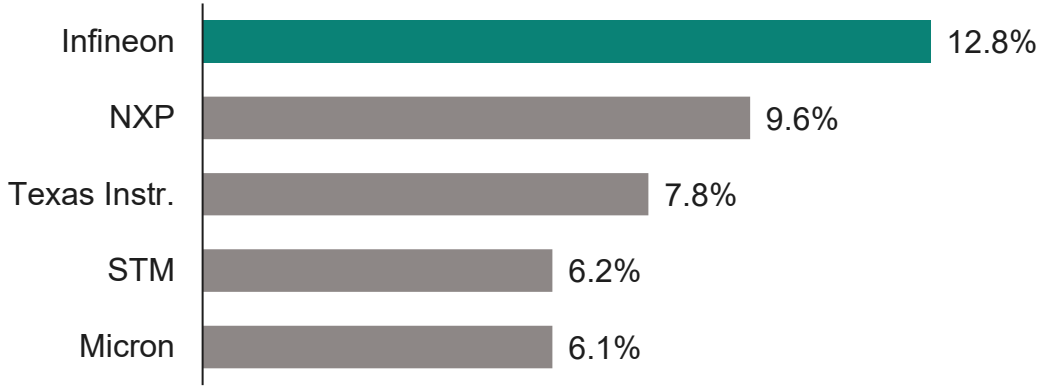
Key customers

APTIV · Astemo · AUMOVIO · BORGWARNER · BOSCH · BYD · DENSO
FORVIA · HL Mando · HYUNDAI · MAGNA · SCHAEFFLER · Valeo · ZF

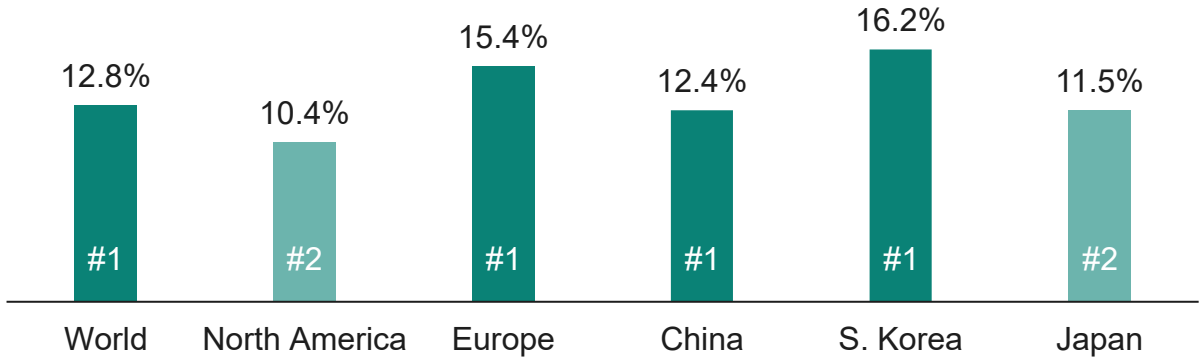
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Infineon's top market position is built on system competence and an industry-leading product portfolio

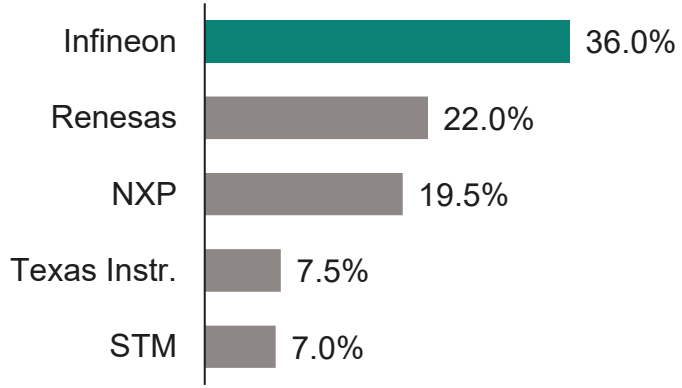
Automotive semiconductors (2025 total market: $74,408m; +6.4% y-y)



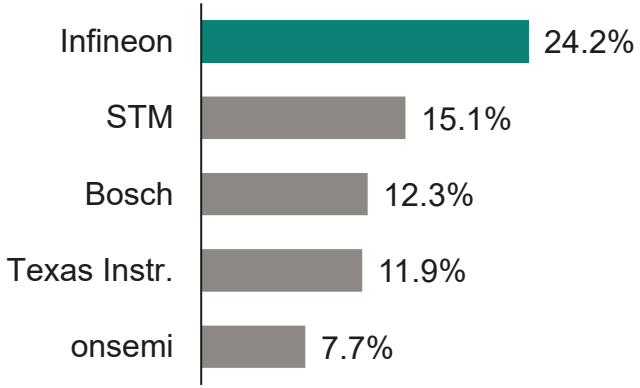
Infineon's 2025 market share and position by region



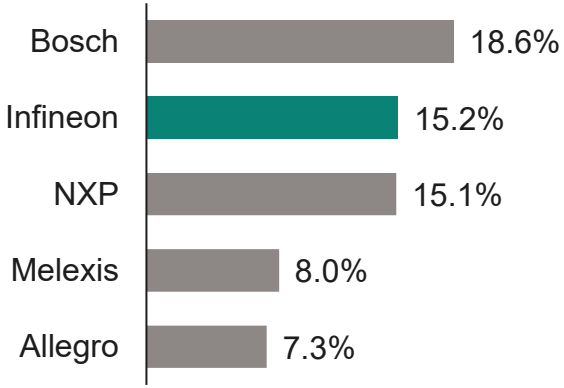
MCUs



Power



Sensors[1]



TechInsights: *Automotive Semiconductor Vendor Market Shares*. April 2026. [1] Sensors: Mobility Global: *Automotive Semiconductor Market Shares 2025*. April 2026.

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Several strong content growth drivers for Infineon in xEV and software-defined vehicles, even at flat LV production

Structural trends fueling our growth

xEV

- Strong volume growth of BEVs and PHEVs
- Increasing share of SiC in traction inverters
- More kW per vehicle lead to higher BoM in inverter

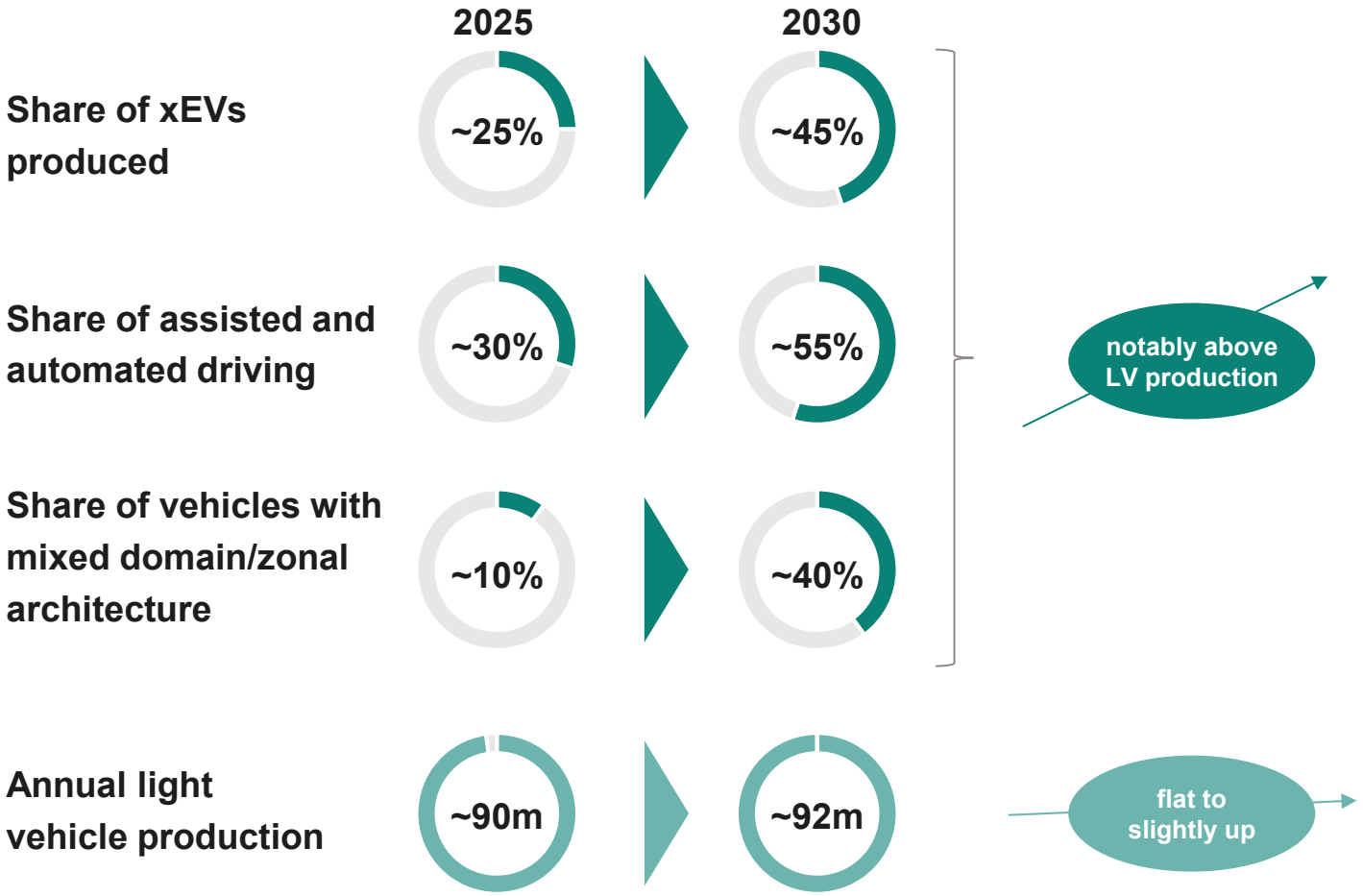
SDV

- Transformation of E/E architecture towards central computing with zonal controllers
- Smart switches for decentralized power distribution
- Software over the air
- Secure connectivity, cybersecurity indispensable
- Functional safety, dependable electronics, redundancy
- ADAS/AD: More sensors, more computing performance

Comfort and premium features

- More loads (motors, heating, cooling etc.)
- More elaborate lighting, both exterior (matrix light) and interior (instruments and ceiling)

Overview of growth vectors until 2030

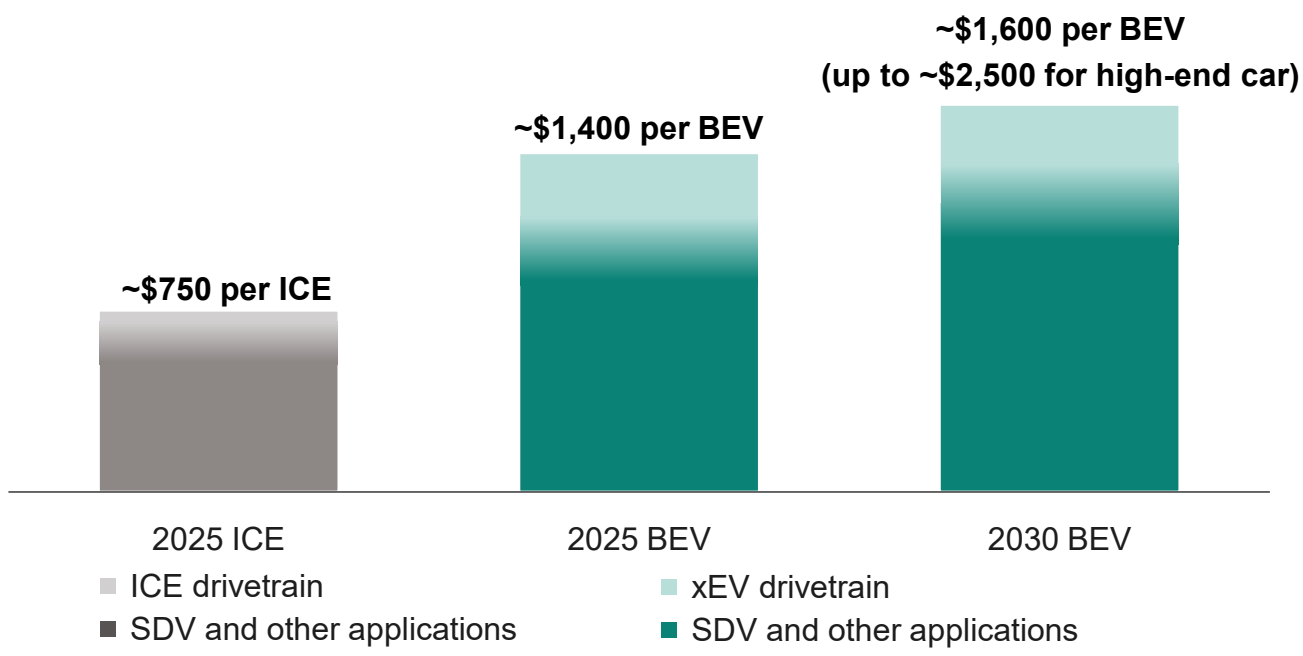


Infineon estimates

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Infineon is the world leader in automotive semis, serving all key applications and benefiting strongly from content growth

Average semiconductor bill-of-material per car in 2025 and 2030



BEV market size growth (vehicle production)



Semiconductors covered by Infineon

Drivetrain applications:

- Traction inverter, OBC, DC-DC, BMS, auxiliaries
- Drivers for BoM increase:
  - SiC and GaN replacing Si
  - more motors and stronger motors per car
    → slight increase in kW per car

SDV and other non-drivetrain applications:

- Domain/Zone
- SDV, incl. E/E architecture and ADAS
- Safety and advanced security
- Comfort and premium
- Connectivity and infotainment

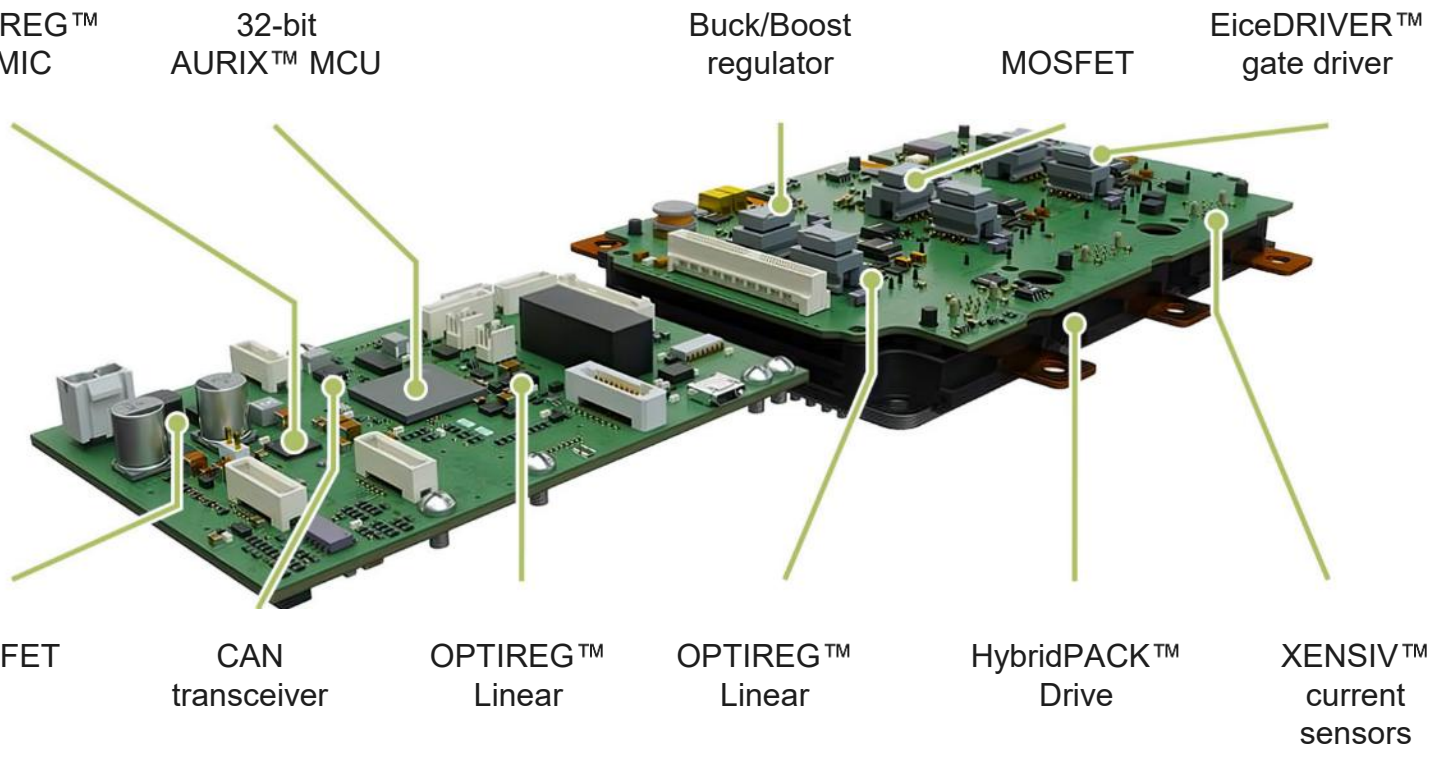
With a growing xEV market and growing non-drivetrain BoM, Infineon benefits twice

Infineon estimate based on Mobility Global E/E & Semiconductor Service dataset – October 2025; November 2025

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Infineon’s broad product portfolio and system understanding enable higher BoM and allow compact designs and fast T2M

Infineon inverter reference design, covering up to 95% of value



P2S (product-to-system approach)

- Reference design for up to 300 kW, further customization possible
- System solution for easy implementation
- Fast time-to-market (T2M)

Freedom of choice

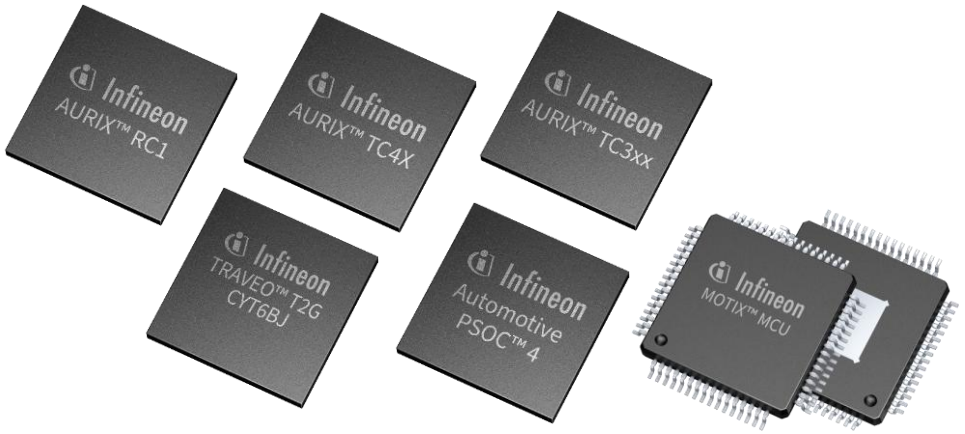
- IGBT and SiC in 750/1,200 V scale up to preferred power class
- HybridPACK™ Drive CoolSiC™ Gen2 continuous operation at 175°C
- EiceDRIVER™ gate driver Gen3 optimized for CoolSiC™
- Optimized 32-bit AURIX™ MCU

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The Automotive Ethernet portfolio strengthens our market leading MCU position and increases offering for zonal architectures

Infineon's unique portfolio of MCU and Ethernet

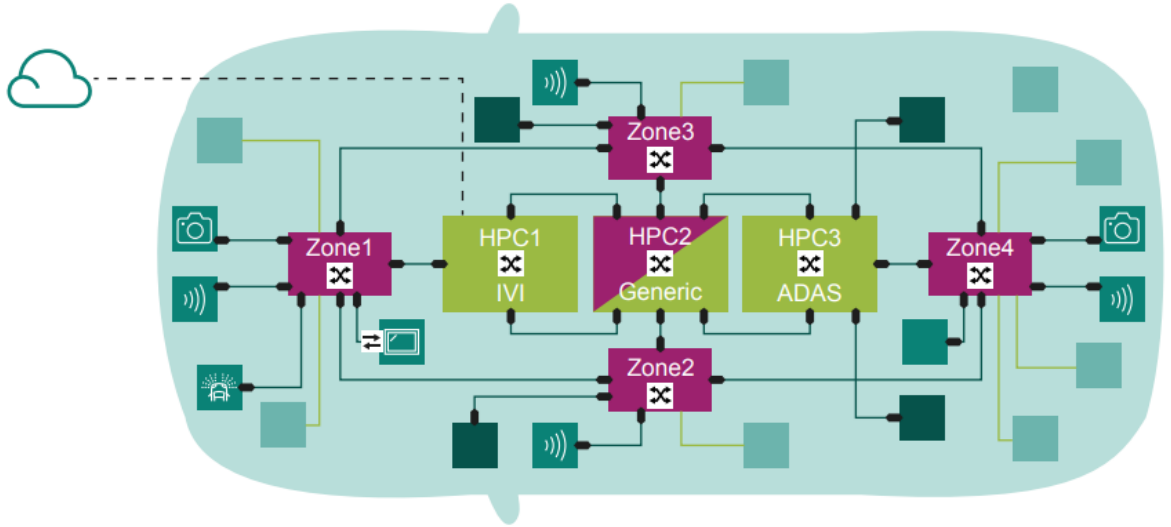
Automotive MCUs



Automotive Ethernet



Components of hierarchical E/E architectures:



High Performance Computing (HPC)

Complex sensors & actuators

Simple sensors & actuators

Zone controller

Control ECU

Scope of Acquisition

PHY

Bridge

Switch

Ethernet

Low-bandwidth network

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Infineon – The number 1 in microcontroller
A proven portfolio, complemented by a new RISC-V foundation.

Established automotive MCU platforms

Proven in the market. Trusted by customers.

TRAVEO™ family



Body, cluster and display

Optimized for body electronics, instrument clusters and HMI applications.

AURIX™ TC3x



Proven automotive control

Market leading across a wide range of real-time automotive applications.

AURIX™ TC4x



Advanced performance

Designed for demanding automotive applications with increased compute and integration.

+

NEW

AURIX™ RC1

A common RISC-V foundation for the next generation.



Software reuse across applications
One common architecture and ecosystem

Scalable real-time compute
Application-tailored performance and integration

Automotive safety and security
Designed for the future of SDV, SDx and beyond

A complete MCU portfolio for today's and tomorrow's designs.

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The new AURIX™ RC1
Redefining real-time control and compute



AURIX™ RC1
Combining the strengths of AURIX™ and TRAVEO™ in one platform

Delivering customer value

1

Simplified development

Highly scalable microcontroller platform based on **RISC-V**, largest SW and partner offering

2

Lower system cost

Feature-cost-optimized portfolio and capabilities to enable **high functional integration** in modern E/E-architectures

3

Higher vehicle efficiency

Enabling **ultra-efficient power management** and **enhanced real-time control**

4

Future proof performance

Superior CPU performance meets AURIX™ architecture – outstanding application performance and **next-level ECU consolidation**

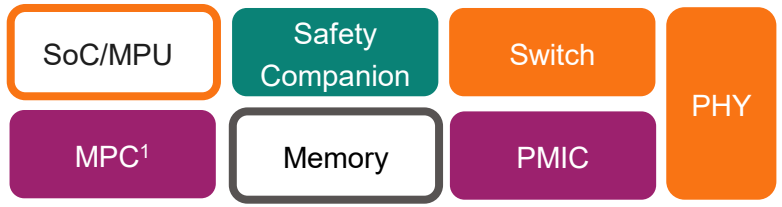
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Enabling the E/E architecture of future SDVs with around $500 content potential per car

Infineon components for hierarchal computing E/E architecture

Infineon BoM[2] potential: ~$500

HPC

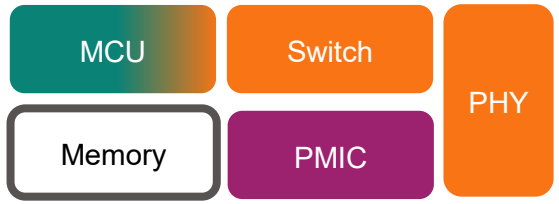


- High-level control for complex, safe and secured driving functions
- High-bandwidth communication

1-3x units per car

~$45 each

Zone

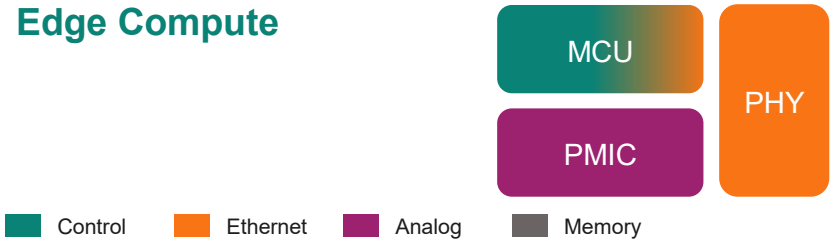


- High-performance real-time control
- I/O aggregation
- Low-latency protocol handling

2-5x units per car

~$35 each

Edge Compute



- Low-/medium-performance real-time control
- End-point communication interface
- Direct connection to sensors and actuators
- Sensor data collection and pre-processing

10-20x units per car

~$15 each

$100 increase in BoM due to Ethernet

[1] Digital multi-phase controller for SoC/MPU | [2] BoM for computing, Ethernet, analog and memory

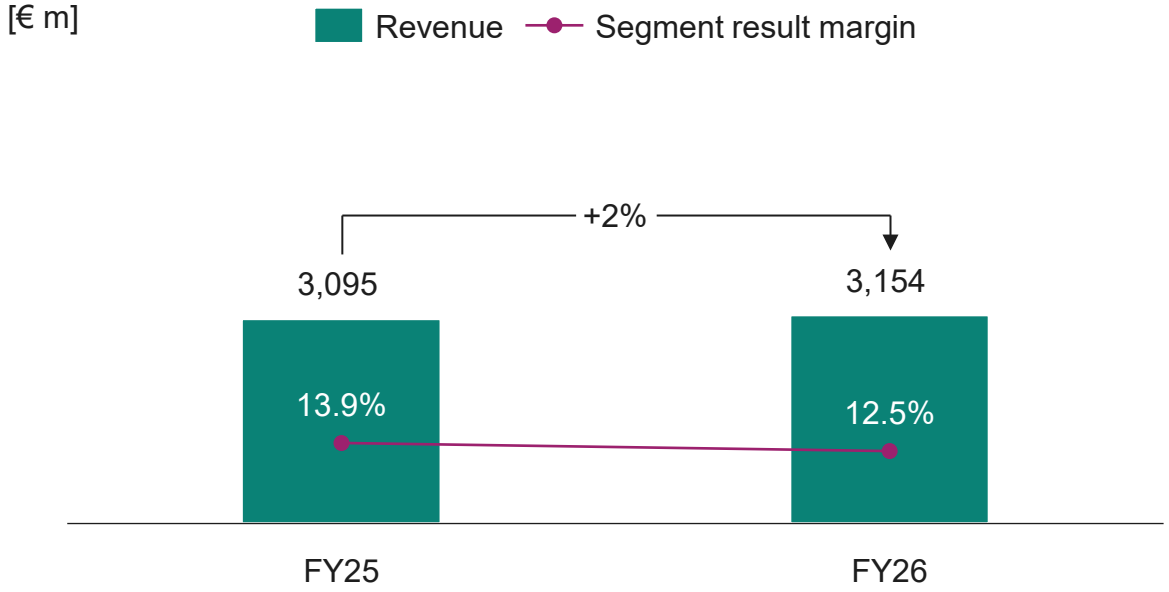
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Edge Systems

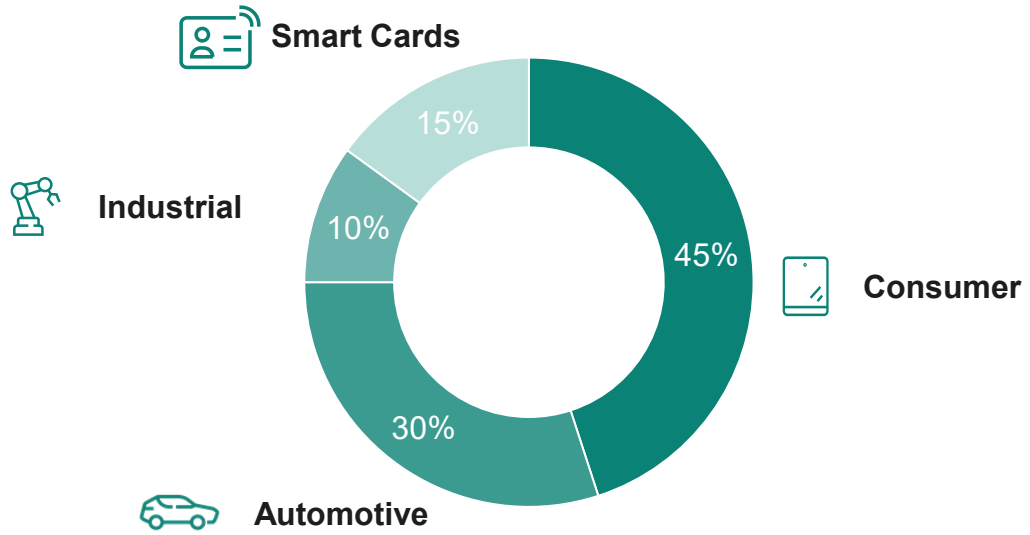


Edge Systems (ES) at a glance

ES revenue and segment result margin



FY26 revenue split by application

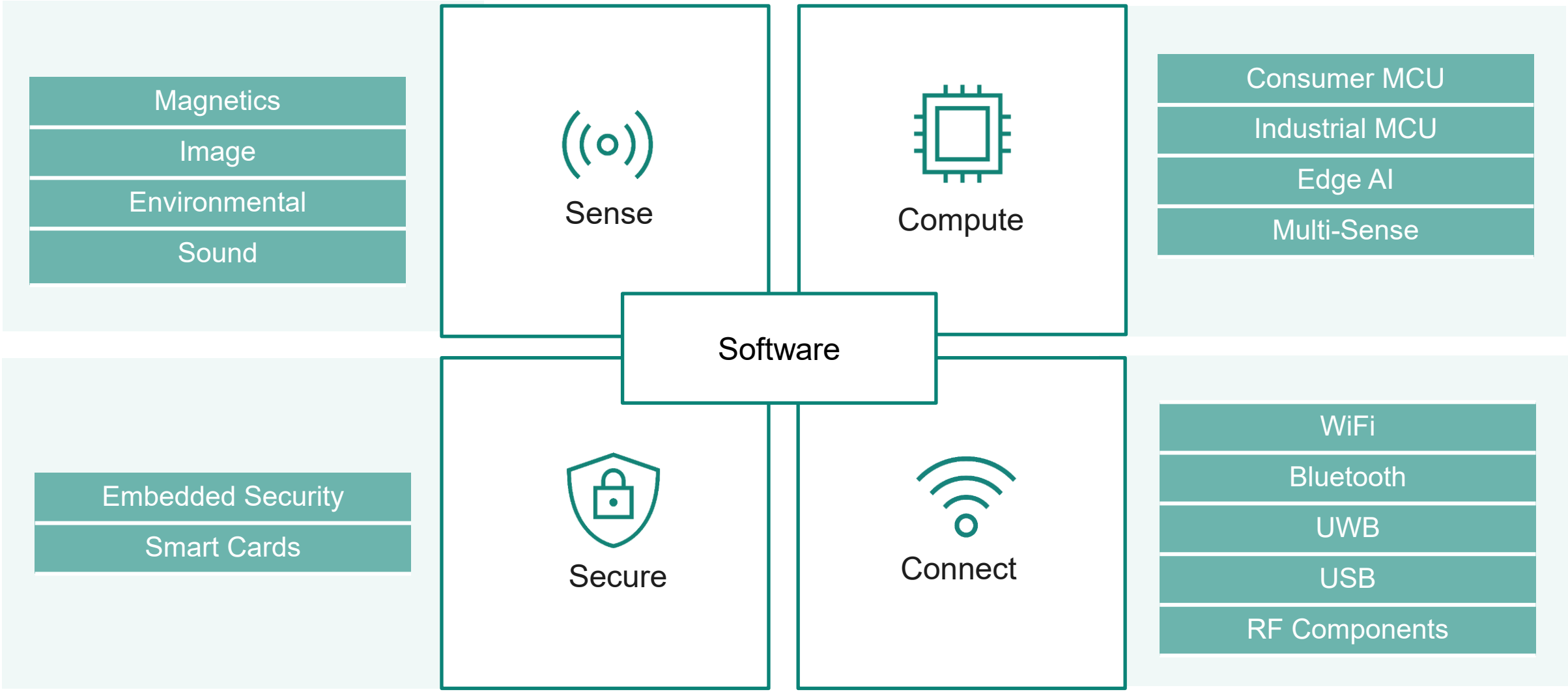


Key customers

amazon | BOSCH | BYD | DELTA | DENSO | ERICSSON | Goertek
Haier | LG | Midea | Nintendo | SAMSUNG | SONY | THALES

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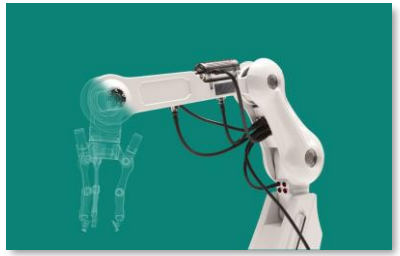
Covering the signal chain with sense, compute, connect, secure components and software



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Infineon's broad portfolio opens system-level opportunities across a wide range of growing applications

Robotics

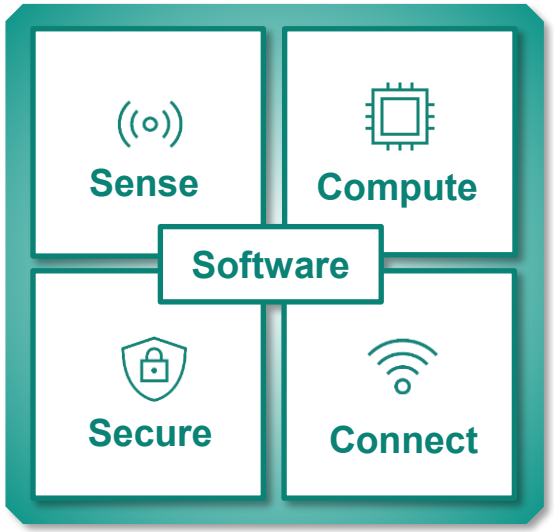


Wearables

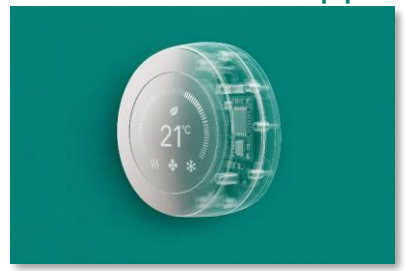


Automotive

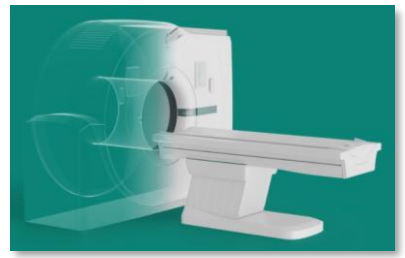




Smart Home & appliances



Digital health



Industrial



Selected applications

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Our XENSIV™ sensor family now includes the ams OSRAM portfolio and brings real-world signals to edge and physical AI



Sensing magnetism

Magnetic sensors

- **Position**
- **Speed**
- **Current**
- **Capacitive**

Giving things the ability to "see"

Image sensors

- **3D ToF** imager
- **Radar**
- **X-ray / CT** ASICs

Sensing the environment

Environmental sensors

- **Pressure**
- **Gas**
- **Temperature**

Capturing audio signals, precisely

Sound sensors

- **Silicon** microphones
- **Vibration**

Broad and leading sensors portfolio serving automotive, industrial and consumer markets

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We empower humanoids to sense, move, act and connect. Safe and secure.

Compute

Edge AI, motor control, Multi-sense MCUs

Connectivity

Wi-Fi, Bluetooth, USB, Ethernet

Power

Power switches incl. Si and GaN, DC-DC conversion, voltage regulators

Security

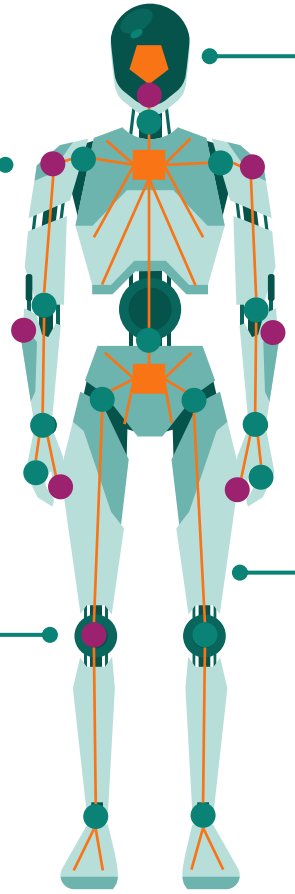
Trusted Platform Module (TPM), Security Controller

Analog

Gate drivers, analog amplifiers, data converters

Sensing

Magnetic, capacitance, current, vibration, pressure, SiMiC, ToF, radar



control & connectivity analog & sensors power

Si SiC GaN

Up to $1000

Infineon's addressable content per humanoid robot

Infineon and NVIDIA accelerate deployment of humanoid robots

- Ethernet-based motor control solution integrated with GaN-based power management
- Digital twin of motor control model, tactile sensing and Time-of-Flight sensing in Isaac Sim
- Certified OPTIGA™ TPM for NVIDIA Jetson Thor™



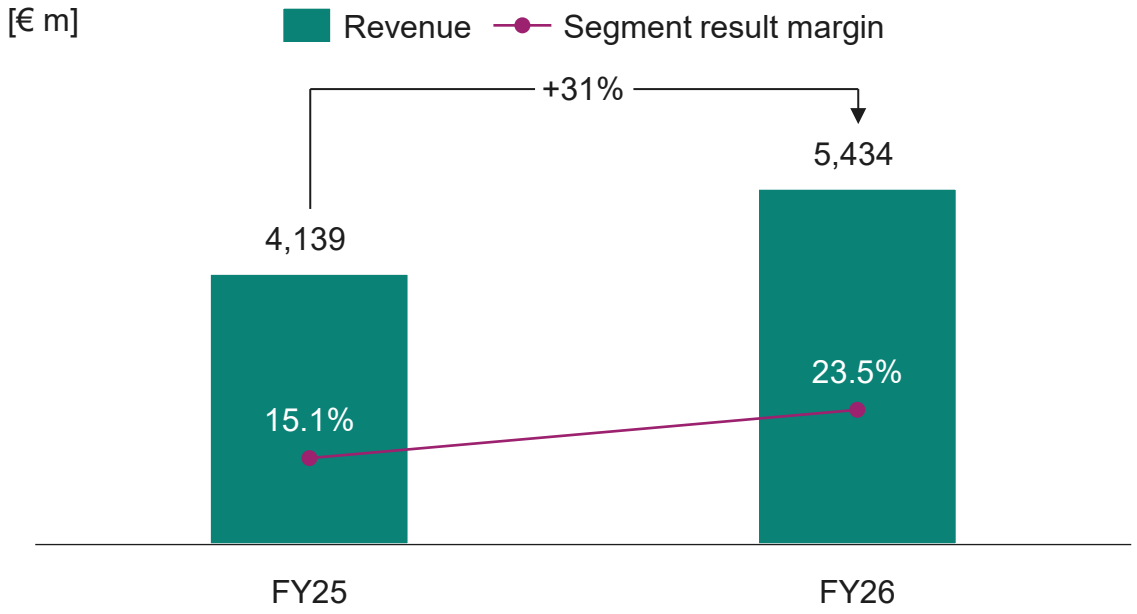
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Power Systems

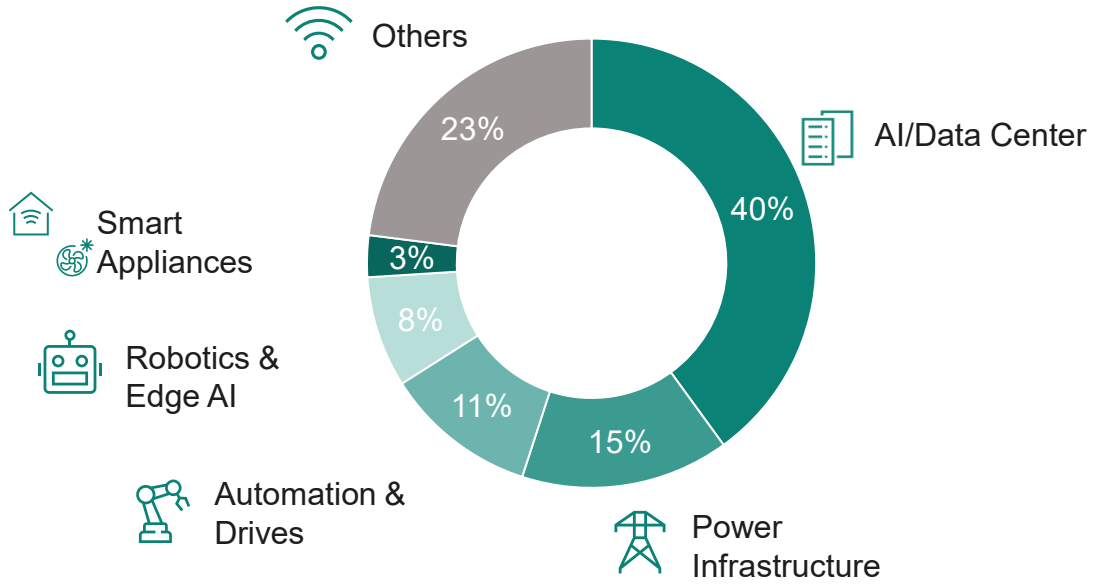


Power Systems (PS) at a glance

PS revenue and segment result margin



FY26 revenue split by application



Key customers

ABB, Advanced Energy, Alpitronic, amazon, Danfoss, DELTA, ERICSSON, flex, Google, HUAWEI, LITEON, SAMSUNG, Schneider Electric, SIEMENS

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Global energy demand is rising fostering a new age of electricity – power infrastructure is becoming a major bottleneck

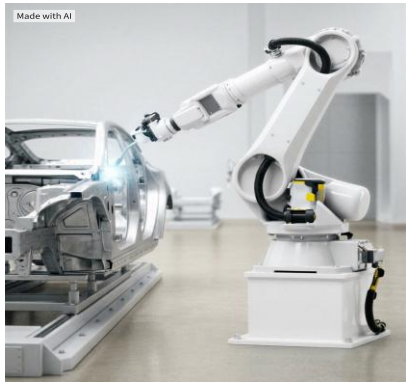
Over **the next five years**, global electricity consumption is forecasted by the IEA to rise from **28 TWh** to about **34 TWh.**

+20%
('26 – '30)

Data Centers



Industry



Transport & Mobility



Buildings



Cooling & Heat pumps



Source: IEA (2026), Electricity 2026, IEA, Paris https://www.iea.org/reports/electricity-2026

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Our semiconductor solutions are vital for the grid of the future – enabling a stable, reliable and efficient power supply

Integrate renewables into grid
by **reliably** connecting remote wind farms and solar plants

Improve energy efficiency
by reducing power losses at every conversion step

Transport electricity efficiently
by using HVDC for long-distance power transmission



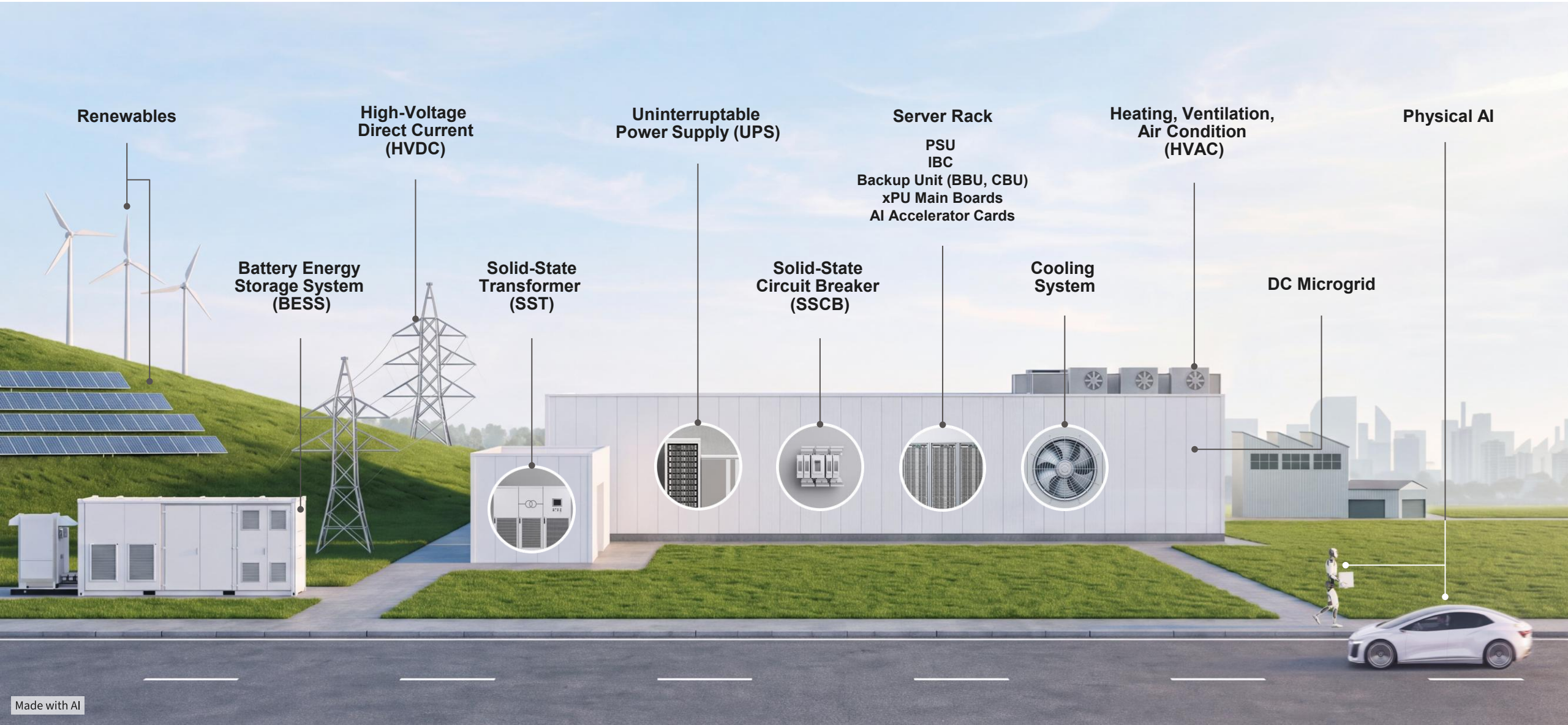
Balance supply and demand
with battery management and power conversion systems

Help stabilize power grids
with flexible transmission systems and grid-forming converters

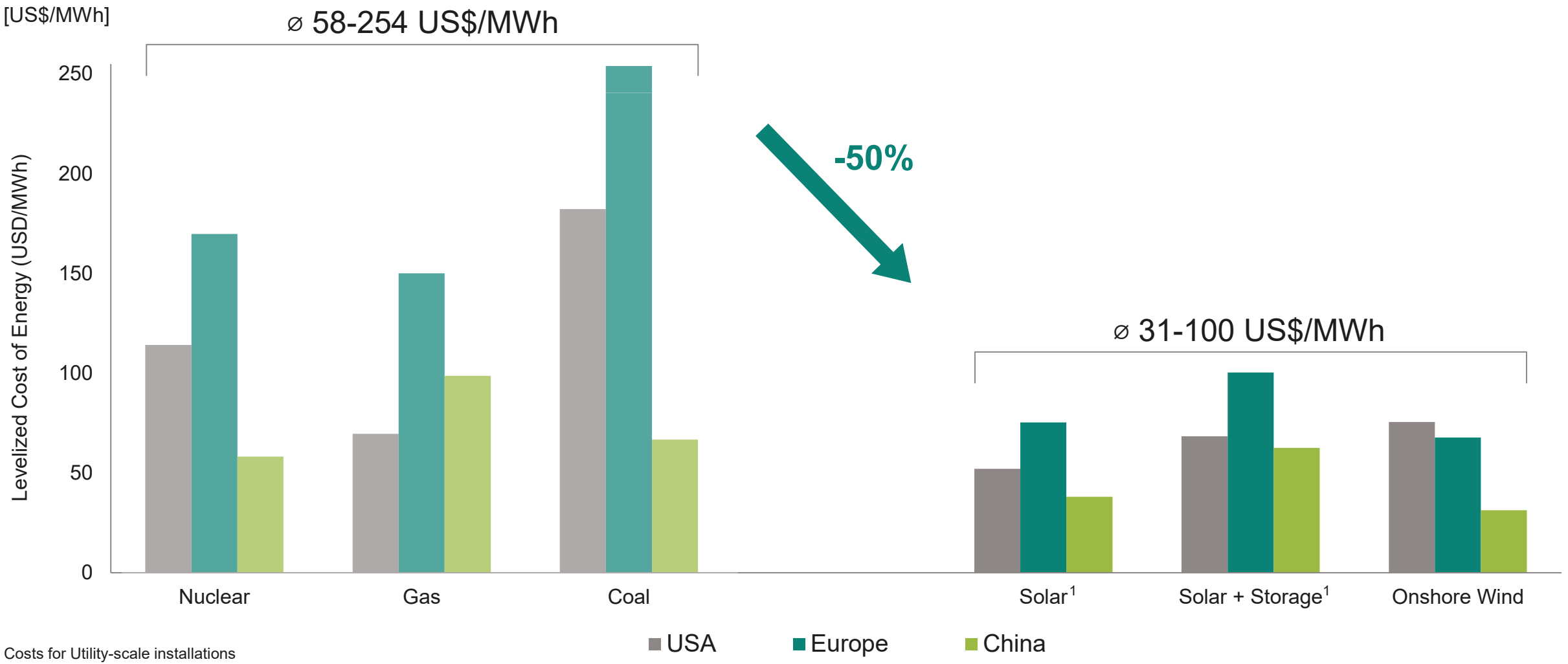
Support bidirectional flow
from smaller power plants or households to the grid

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The age of electricity calls for semiconductors



Renewables are on average the cheapest source of energy



[1] Costs for Utility-scale installations
Based on Wood Mackinzie LCOE Levelized Cost Of Energy dataset, 2024

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Commercial and Utility Storage Solutions with strong growth potential

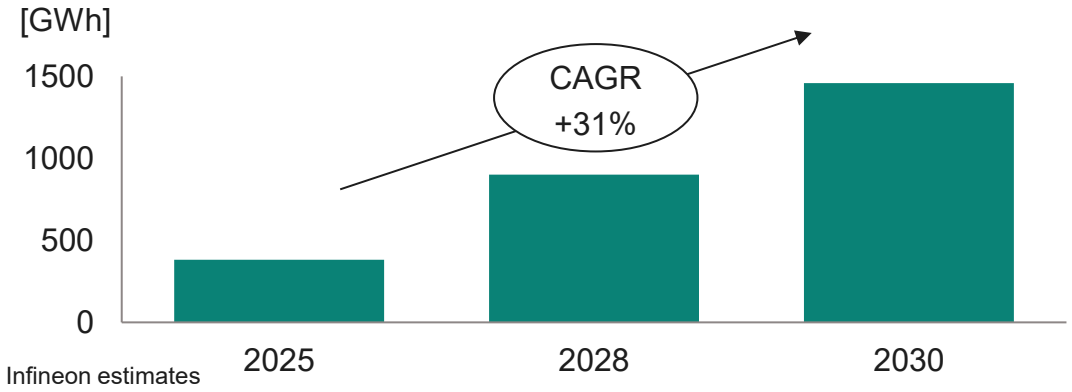
Infineon's semiconductor content for energy storage solutions (ESS)

power	– IGBT discretes – SiC MOSFETs – Low & medium power modules – High-power modules
control & connectivity	– MCUs – Connectivity chips
analog & sensors	– Gate drivers – Current sensors

>€2,500 per MW



Global ESS battery shipment forecast



Close engagement with key players

- ESS inverter companies
- System integrators
- Battery OEMs



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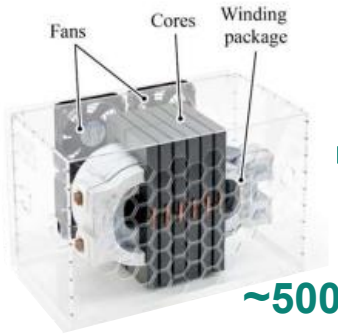
Solid-state transformers: new application for semiconductors with significant additional market potential

Conventional transformer



~20 t

Solid-State transformer (SST)



~500 kg



~40x lighter[1]

~14x smaller[1]

~50% faster construction time

SiC

EasyPACK™



Conventional transformer market **>USD 15bn**

Infineon expects that **SST will replace a portion of the market**, specifically small power transformer with an expected market of **>USD 1bn in 2030**

Early involvement with leading electronics companies and hyperscalers on architecture & design in Europe, Americas and Asia, e.g:

DELTA DG MATRIX solaredge

[1] Comparison refers to multi modular inverter (dual stage with HFT) based on own estimations.

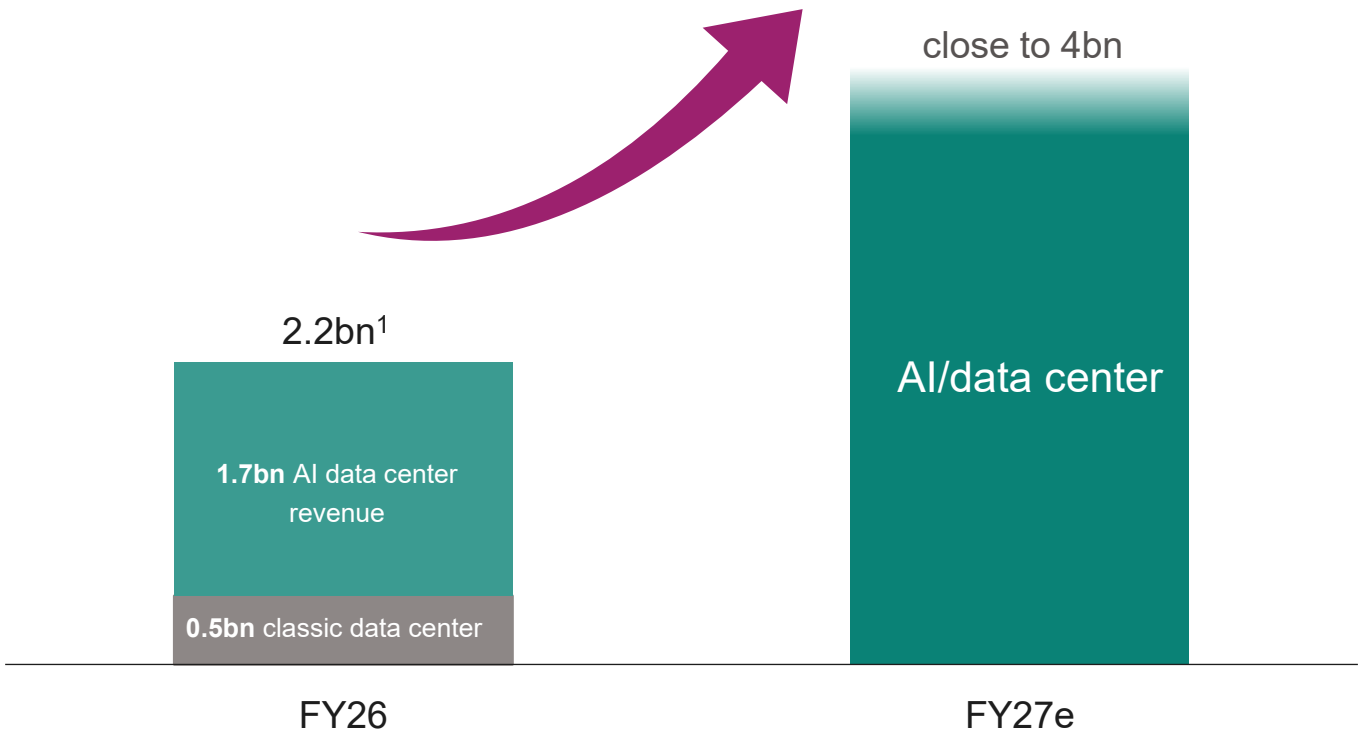
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Continued strong growth of our AI/data center revenues

Infineon is growing driven by buildouts and significant content per watt

Revenues from powering AI/data center

[€ bn]



We **achieved €2.2bn of total data center revenue** in FY26, almost **doubling** vs. FY25

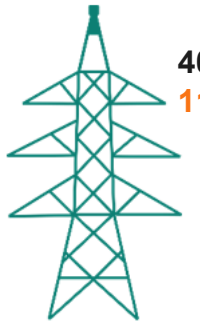
We expect **FY27 revenues close to €4.0bn** including traditional data center business

Infineon AI **power content** per **kilowatt** in the range of **$100-250 growing further from $175/kW** average **today**

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With its energy efficient power semiconductors Infineon is serving all AI-related power conversion from grid-to-core

Server power flow for Gen 1 / Gen 2 / Gen 3 server rack architecture



400 V AC
11 kV AC

Power supply

Power supply unit (PSU)
Battery backup unit (BBU)
Solid state transformer (SST)

Controllers,
drivers, switches



48 V DC
800 V DC

1st stage

Intermediate conversion
(IBC) and protection

Controllers, drivers,
switches, protection

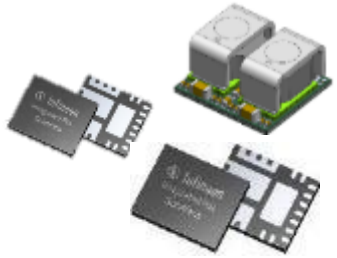


12 V / 6 V

2nd stage

Voltage Regulation
lateral, vertical, embedded

Controllers, power stages,
POLs, modules



~1 V

AI

Processor

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Innovative PSU system solutions leverage system expertise and IP to deliver industry-leading performance and efficiency

Infineon's solutions range from 3 kW to 30 kW

3.3 kW
1-phase PSU
η 97.4%
98 W/in³
Si SiC GaN



8 kW
1-phase PSU
η ~97.5%
100 W/in³
Si SiC GaN



12 kW
1-phase PSU
η ~97.5%
113 W/in³
Si SiC GaN



18 kW
3-phase PSU
η ~97.5%
100+ W/in³
Si SiC GaN



27 kW
3-phase PSU
η 98+%
100+ W/in³
Si SiC



30 kW
3-phase PFC
η 99+%
~270 W/in³
SiC GaN



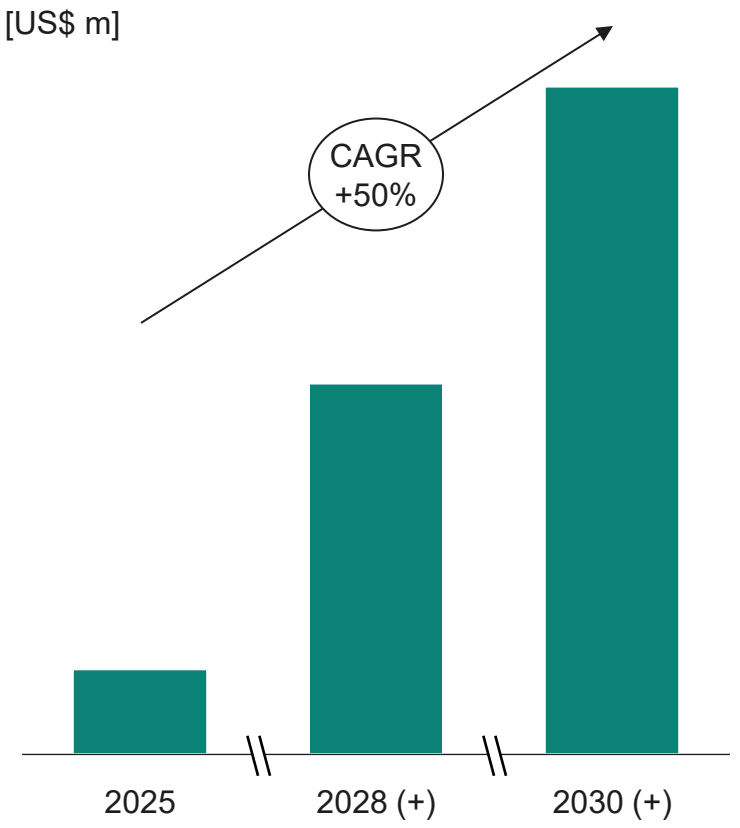
Rising power demands require the transition to advanced three-phase PSU architectures

1-phase PSU | 3-phase PSU

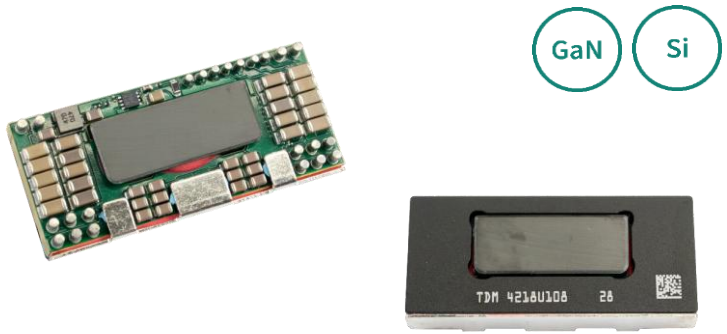
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Infineon offers a broad portfolio of HV & MV IBCs for current and future AI server rack architectures

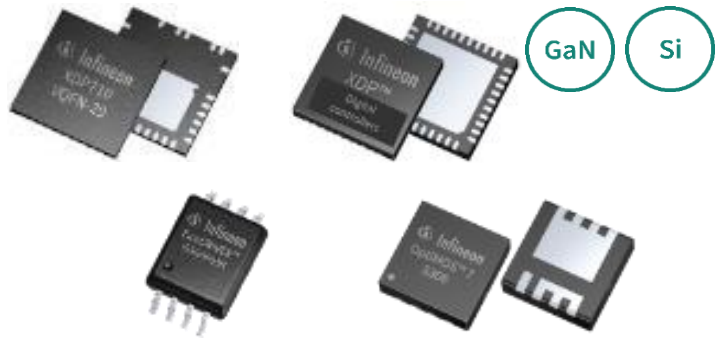
SAM IBC Market



Infineon IBC Module for AI



Discretes



Meeting customer requirements

1. With a wide range of **IBC topologies**, Infineon is serving a multitude of data rack configurations while ensuring cost-effectiveness
2. **Quality and Reliability** to improve mean time between failures in complex systems
3. **Power density** as GPU power increases
4. **Efficiency for** total cost of ownership
5. **Thermal Management** in air / liquid cooled environments
6. **Supply security** with 2nd source and fast time to market

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Highest-density VRM modules enable true vertical power delivery adjacent to the processor

Breaking the speed and density barrier - Next-gen VRMs achieve 3 A/mm2 and more

>x4

x2

1.0 A/mm²
1 Phase
1st Gen module
2024

1.5 A/mm²
2 Phases
2nd Gen module
2024

2.0 A/mm²
4 Phases
3rd Gen module
2025

2.0 A/mm²
4 Phases
3rd Gen module
TLVR
2027

2.5 A/mm²
4 Phases
Slim vertical
power module
2027

3.0 A/mm²
Dual-Phase
High density
vertical module
2027

> 3.0 A/mm²
Substrate-
attached vertical
module
2028

> 4.0 A/mm²
Substrate-
embedded
module
2028



today

tomorrow

Future Solutions
>3.0A/mm²

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We are shaping the quantum era

Quantum Computing
Quantum Processing Units (QPU) based on platforms in ion traps, superconducting and semiconductor-based spin technologies

Quantum Sensing
Silicon carbide competence driving precision, sensitivity, and miniaturization (System-on-a-Chip) of quantum sensors

Quantum-Secure Future
World's first common criteria certification for a security controller for future-proof protection and digital trust

Quantum Collaboration
Trusted partner for researchers, industry, and companies powering a strong quantum ecosystem from technology to real-world applications



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Selected financial figures



Outlook for Q1 FY27 and FY27

	Outlook Q1 FY27[1]	Outlook FY27[1]
Revenue	~€4.6bn	~€20bn
Adj. Gross Margin		mid-to-high 40s %
Segment Result Margin	~23%	mid 20s %
FCF Adj. FCF		~€1.8bn/ ~€2.2bn
Investments		~€3.0 - €3.5bn
D&A		~€2.2bn[2]

[1] Based on an assumed average exchange rate of $1.15 for €1.00
[2] Including the amortization of approximately 300 million Euros from purchase price allocations

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Modular investment approach for long-term value creation – FY27 focused on expedited ramp-up of new capacity

Infineon investments[1] FY27



Capacity investments

– Smart power and logic: enabling further growth for ”powering AI” and analog/mixed-signal products

Shell investments

– Dresden module 4

Research and development

– IFRS capitalization of development cost

Basic investments

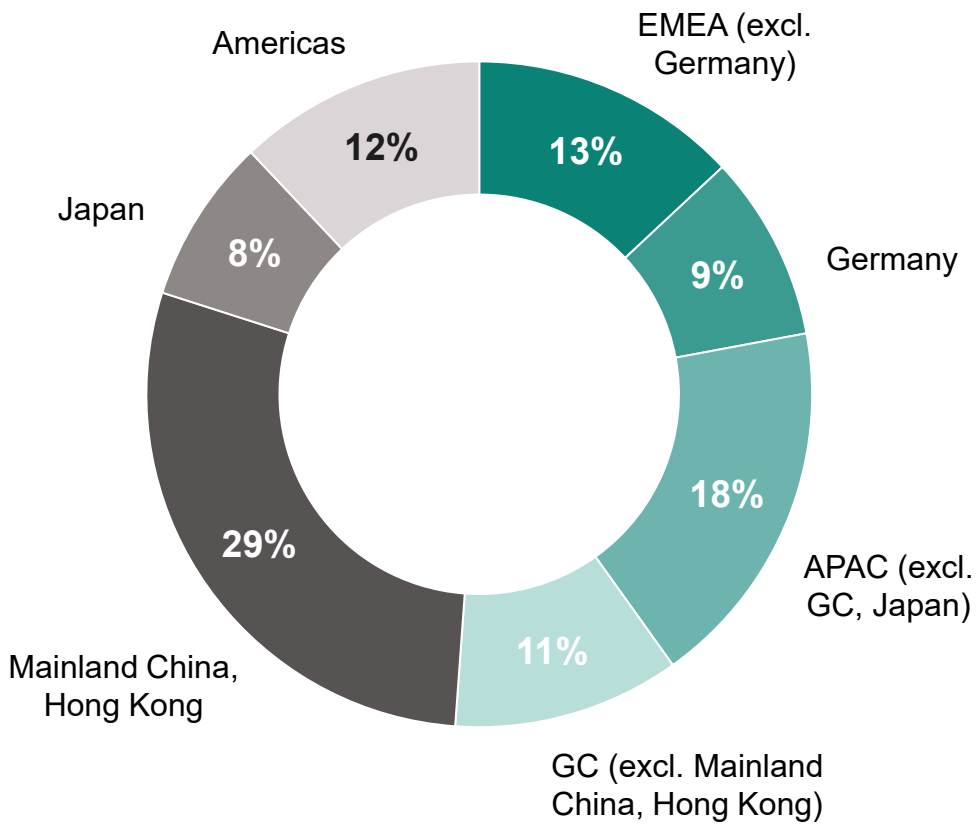
– Maintenance, process optimization, quality, IT

[1] Investments are defined as the total amount invested in property, plant and equipment and in other intangible assets, including capitalized development costs

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Strong presence in all regions; well-balanced customer portfolio; no customer represents more than 10% of total sales

FY26 revenue by region[1]



[1] Based on sold-to logic

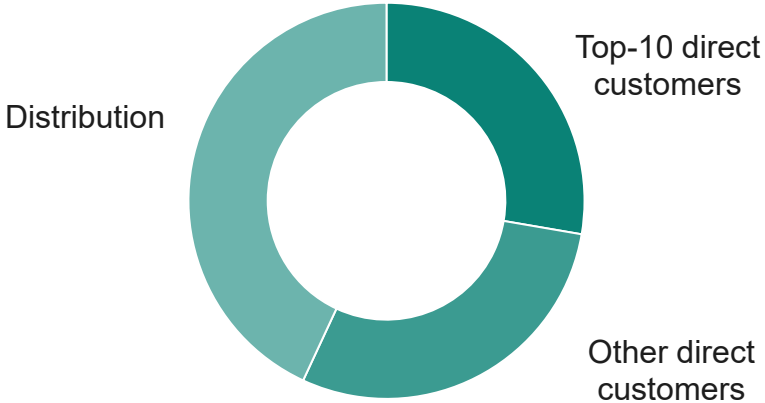
Revenue by sales channel

Distribution partners[2]

Arrow, Avnet, intron 英恒, JCT, Macnica, Marubun, NEXTY Electronics, TTI, 威健 WEIKENG, wpg

Top-10 direct customers[2]

APTIV, AUMOVIO, BOSCH, DELTA, FORVIA, Goertek, HYUNDAI MOTOR GROUP, SCHAEFFLER, Valeo, ZF



EMS partners[1]

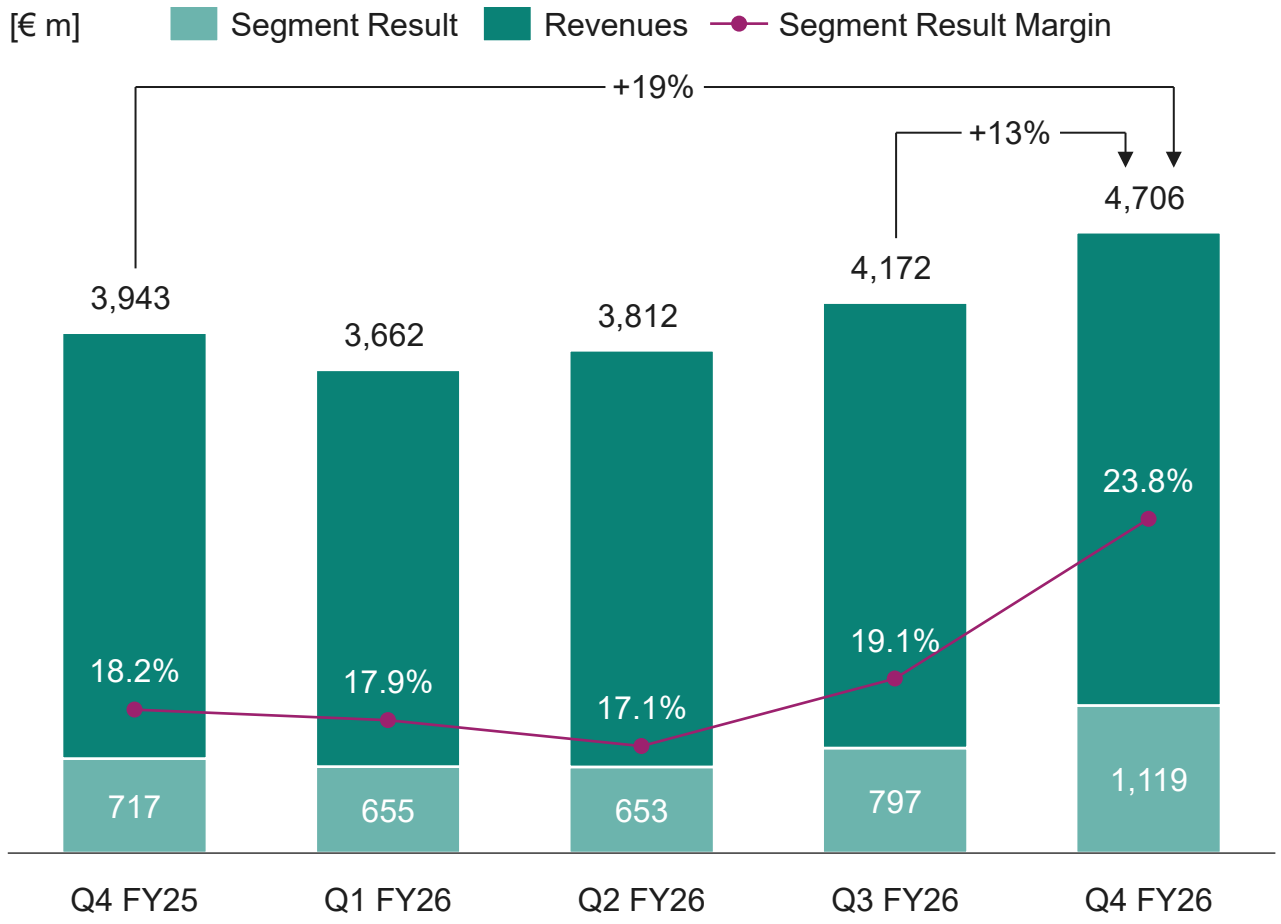
FOXCONN HON HAI TECHNOLOGY GROUP, flex

[2] In alphabetical order

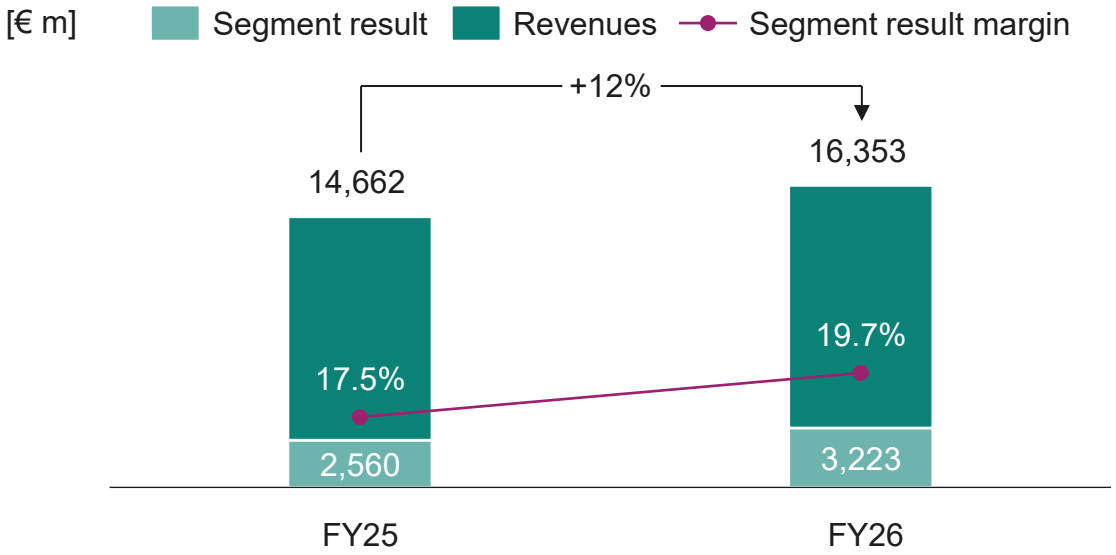
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Group financial performance

Revenues and Segment Result



Revenues and Segment Result FY26



USD exchange rate

Average revenue exchange rate ø USD/EUR

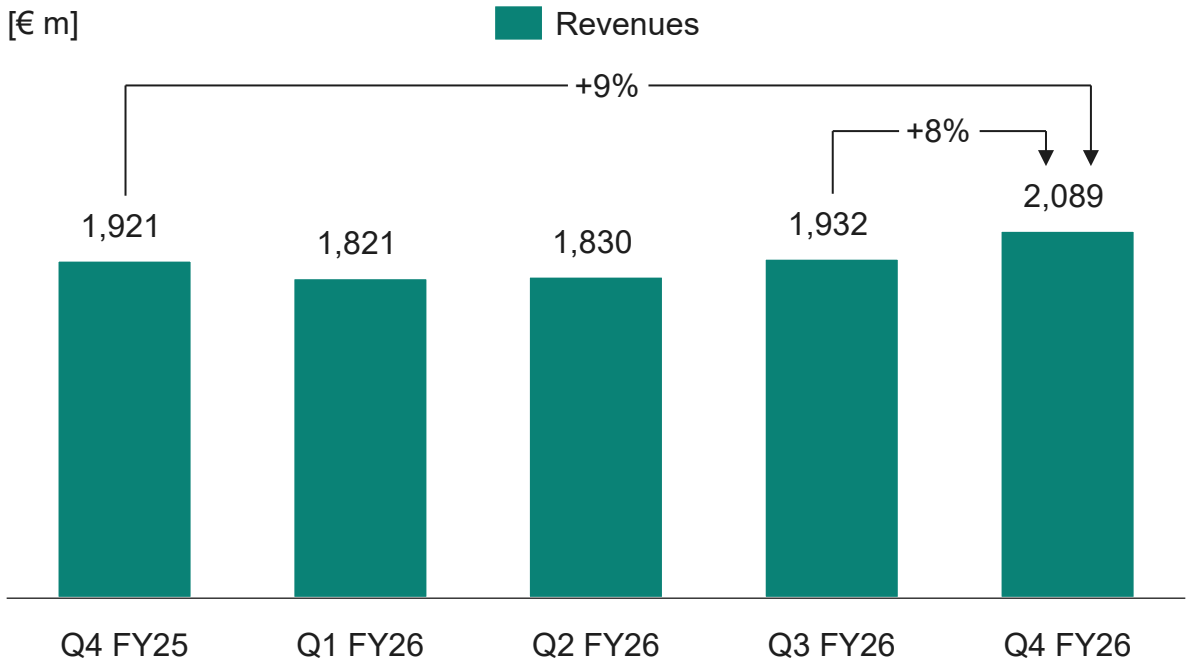
Q4 FY25	Q3 FY26	Q4 FY26	FY25	FY26
1.17	1.16	1.15	1.11	1.16

[1] See notes for definition

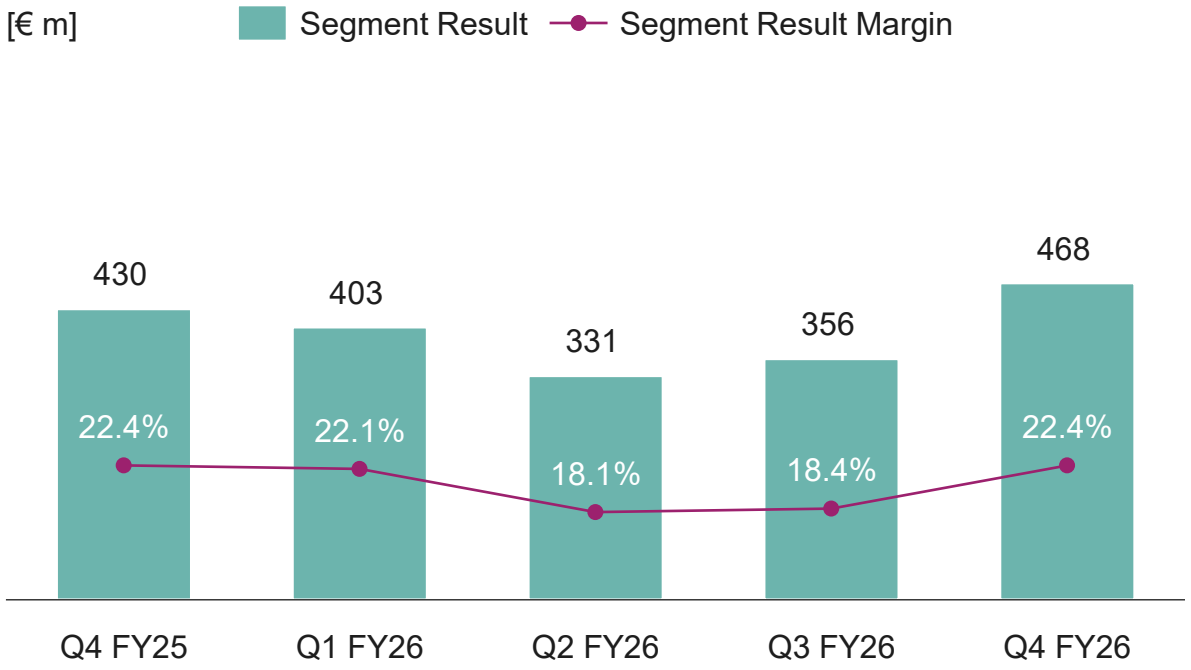
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Automotive (ATV)

Revenues



Segment Result

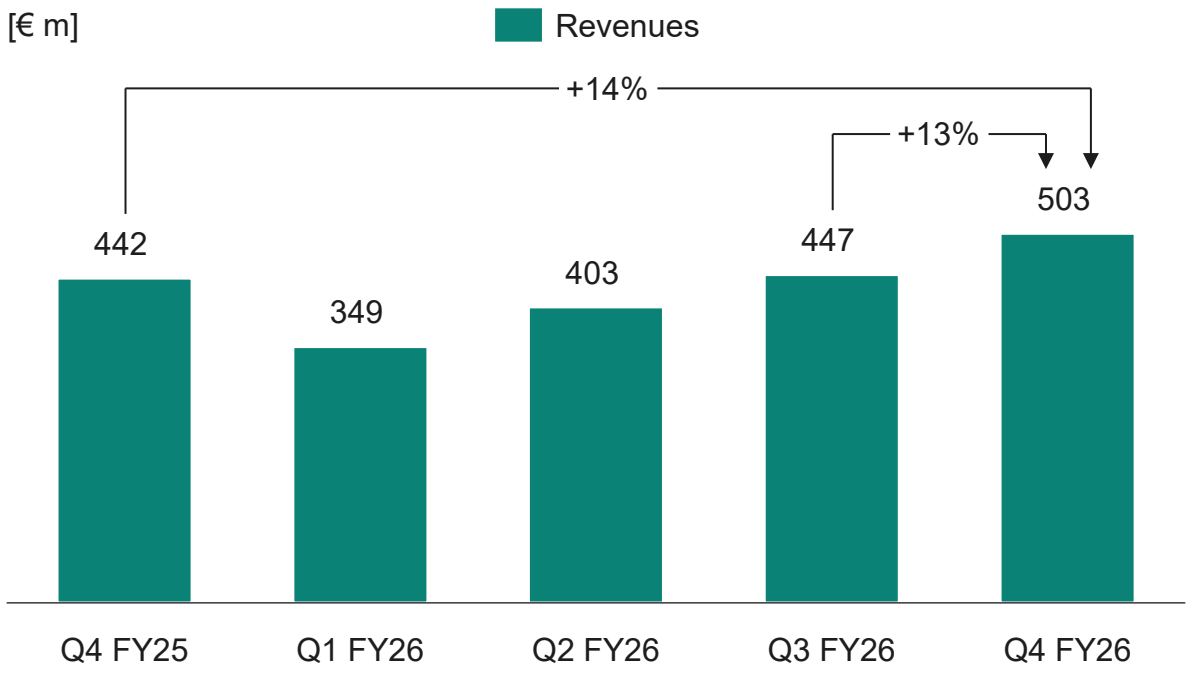


- Q-o-Q revenue growth driven mainly by microcontrollers, smart power components and MOSFETs
- Segment Result Margin benefiting from mainly higher volumes and some positive mix and pricing effects
- Rising order intake driven by structural content growth from SDVs and xEVs

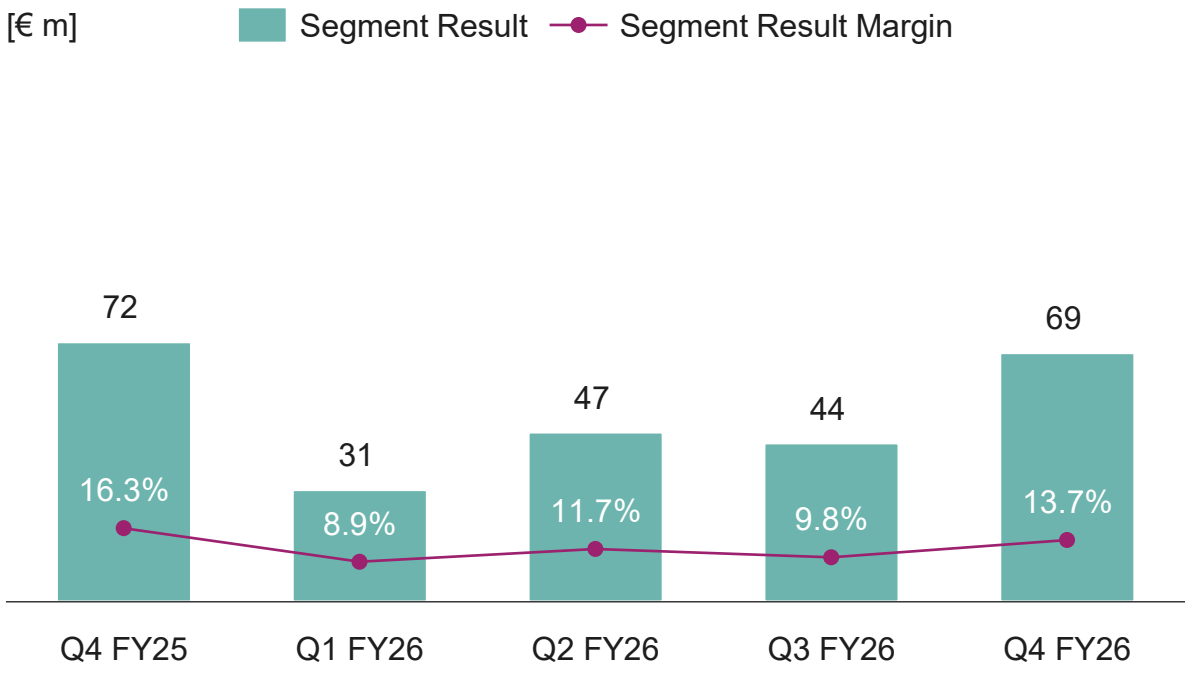
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Green Industrial Power (GIP)

Revenues[1]



Segment Result[1]



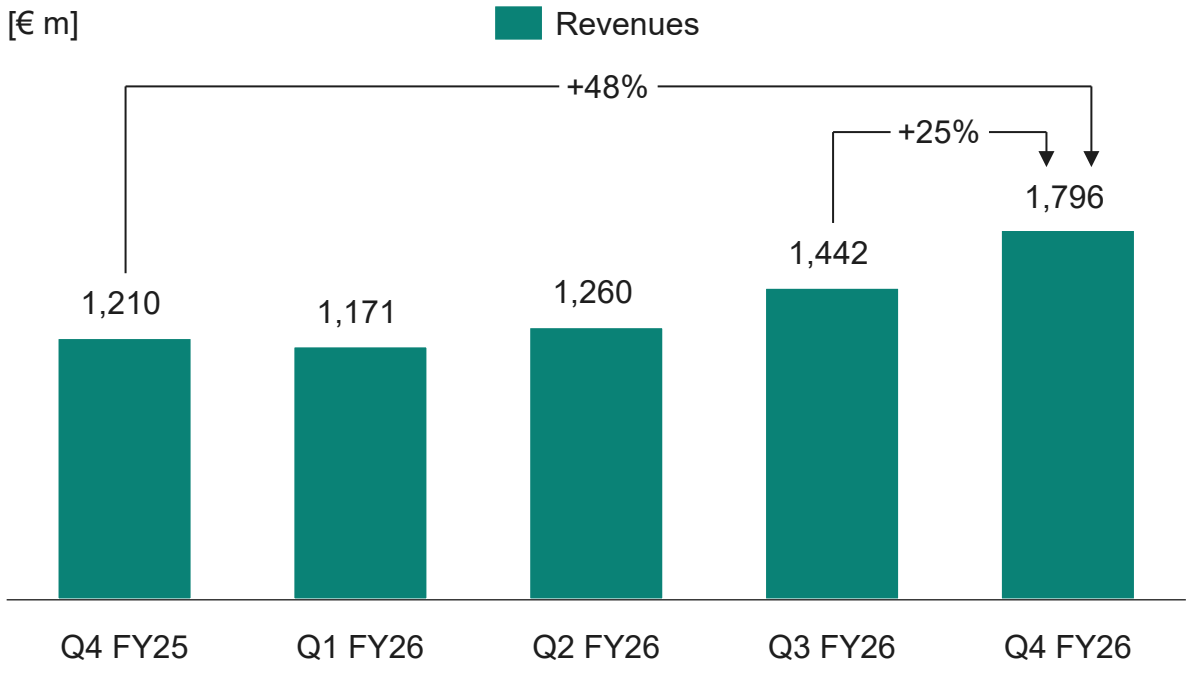
- Third consecutive quarter of double-digit revenue growth, with all application areas contributing
- Segment Result improvement driven by higher volumes and favorable product mix
- Power infrastructure remains the strongest structural growth engine, supported by grid modernization, renewables and datacenter buildouts; industrial recovery broadening

[1] Figures have been historically restated to reflect "Power Drivers & Signal ICs" product line transfer of from GIP to PSS

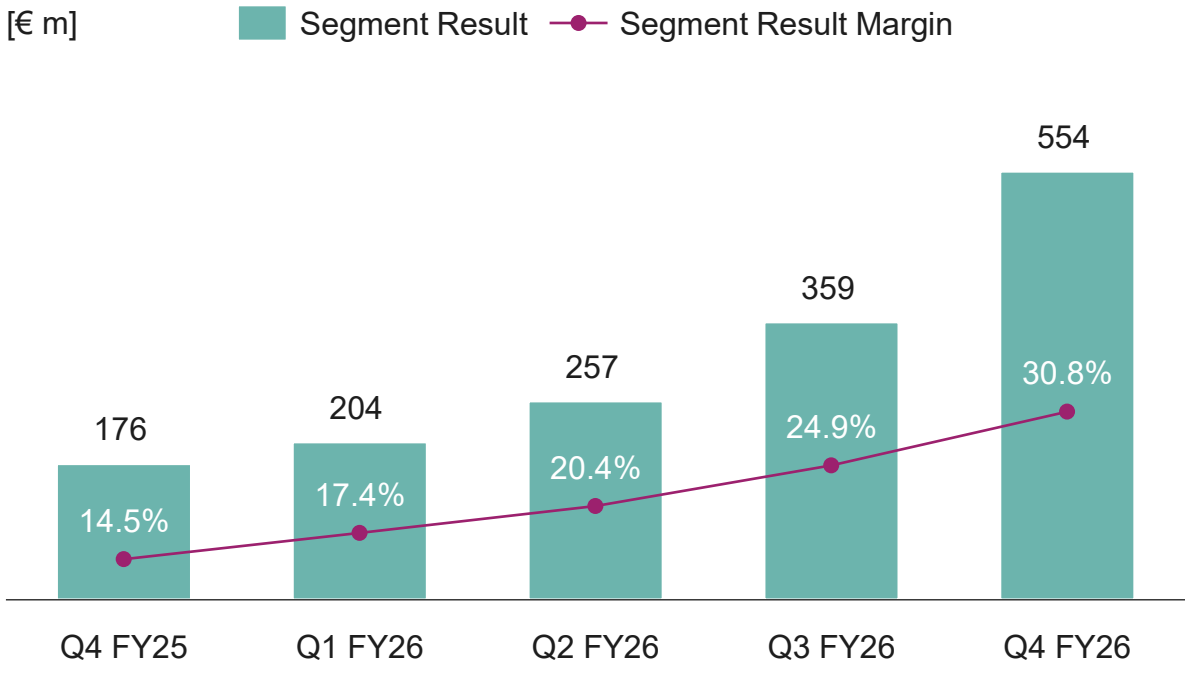
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Power & Sensor Systems (PSS)

Revenues[1]



Segment Result[1]



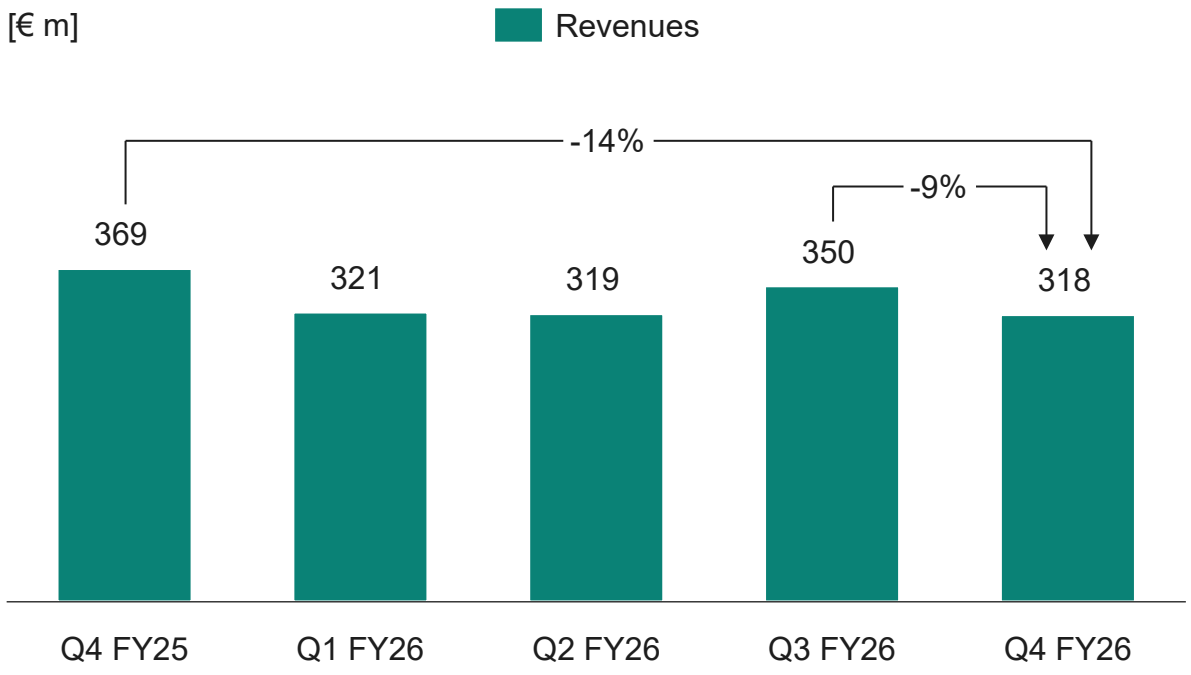
- Stellar quarter with significant profitable growth, driven by AI power leadership
- Segment Result Margin expansion due to significant volume increase, positive mix and pricing effects
- FY26 dedicated AI power revenue of €1.7bn; overall data center revenue around €2.2bn. Further strong FY27 data center demand from customers

[1] Figures have been historically restated to reflect "Power Drivers & Signal ICs" product line transfer of from GIP to PSS

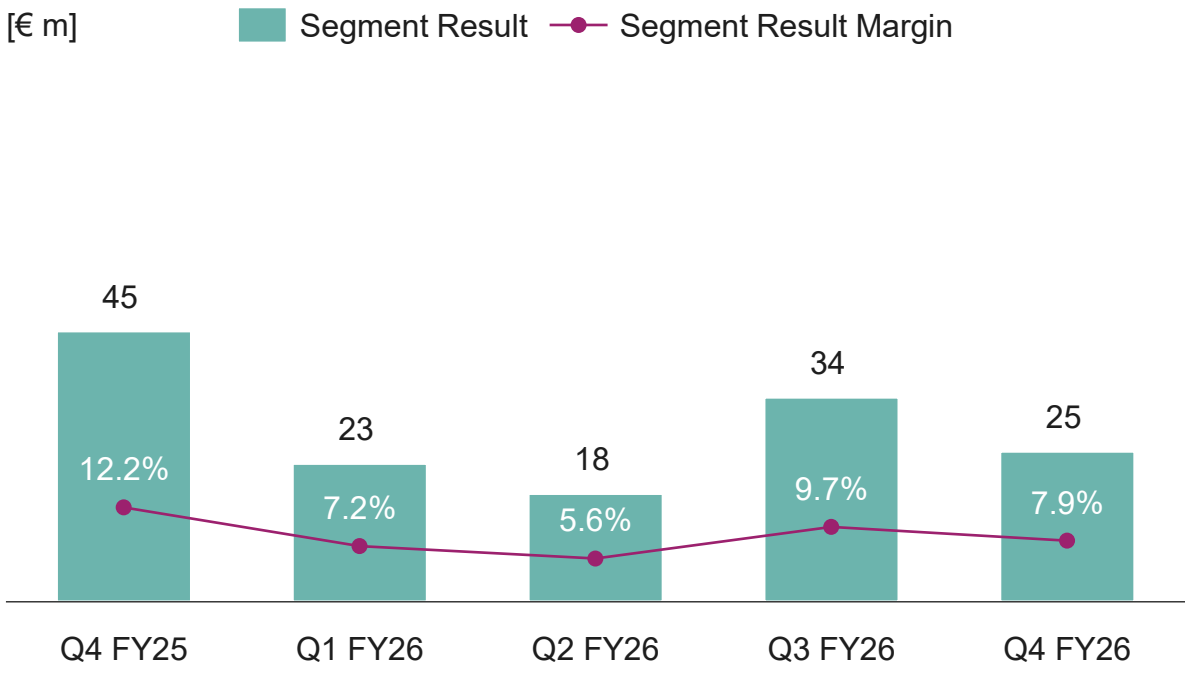
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Connected Secure Systems (CSS)

Revenues



Segment Result



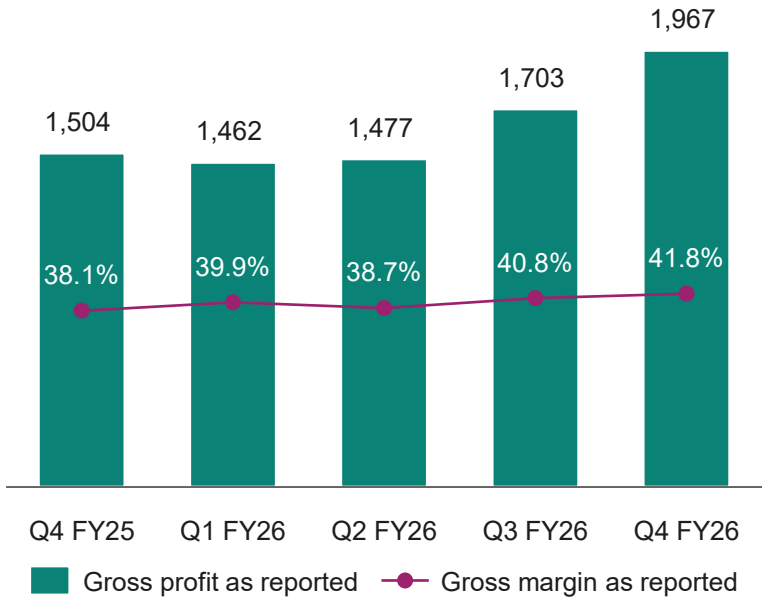
- Revenue decline due to temporarily fluctuating project business and supply constraints, partly offset by eSIM ramp and improving compute and connectivity demand
- Segment Result Margin reflecting lower revenue
- Recovery signals broadening; Edge AI driving demand for secure, energy-efficient system solutions combining microcontrollers, software, connectivity and security

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Gross margin and Opex

Gross profit

[€ m]



Therein Non-Segment Result charges
[EUR m]

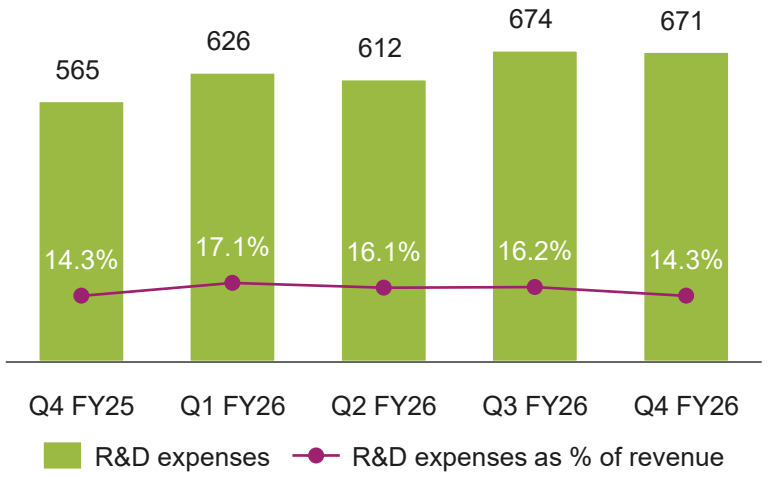
99	113	85	84	155

Adjusted gross margin

40.7%	43.0%	41.0%	42.8%	45.1%

R&D

[€ m]

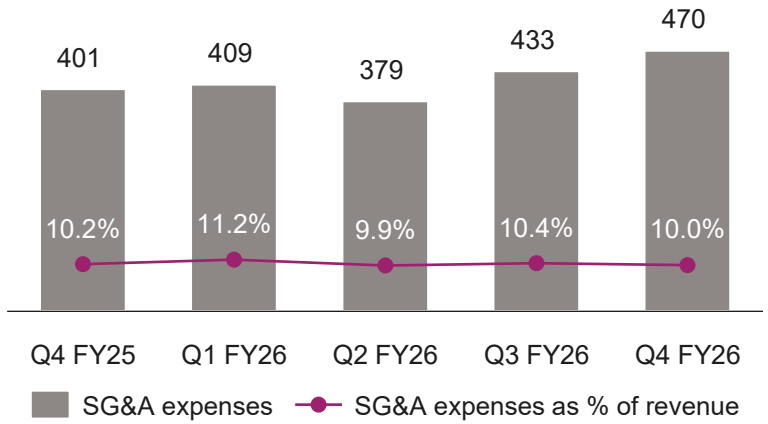


Therein Non-Segment Result charges
[EUR m]

17	35	29	44	47

SG&A

[€ m]



Therein Non-Segment Result charges
[EUR m]

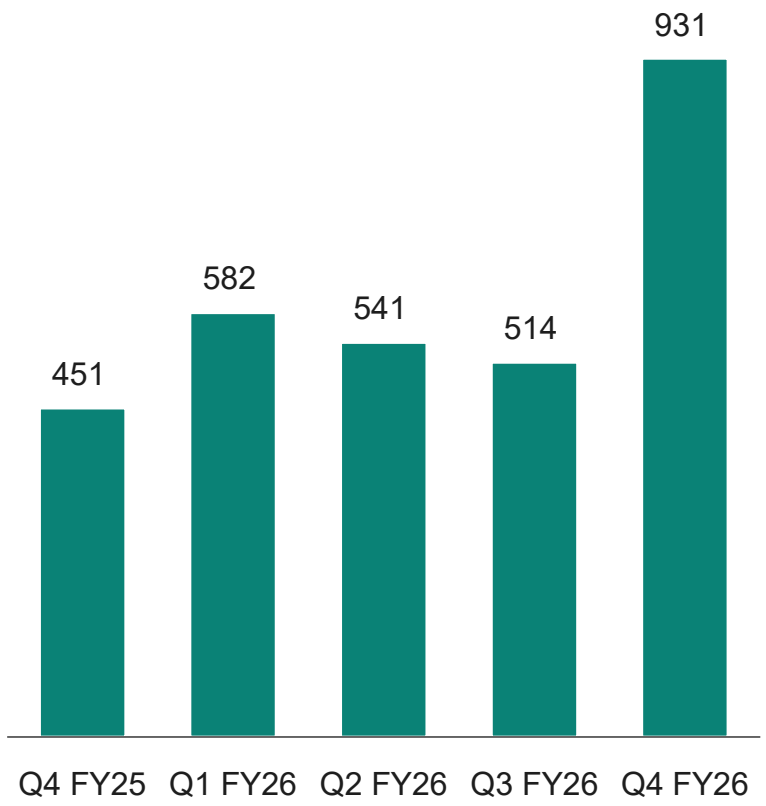
67	77	52	72	92

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Investments, Depreciation & Amortization and Free Cash Flow

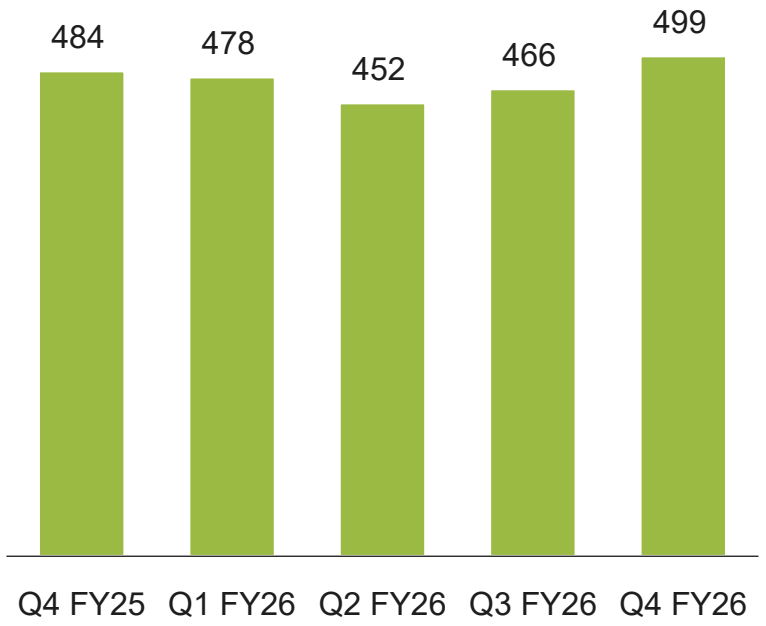
Investments

[€ m]



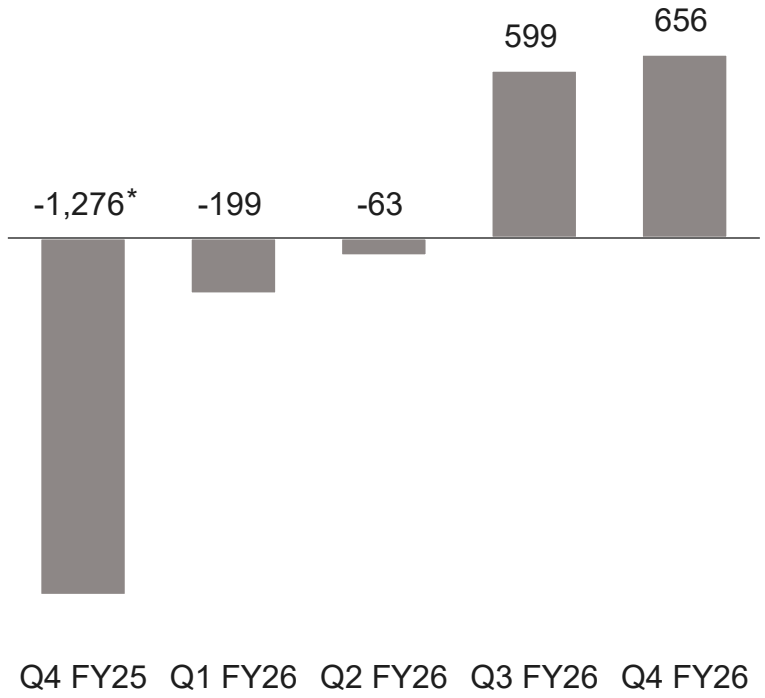
Depreciation & Amortization

[€ m]



Free Cash Flow

[€ m]

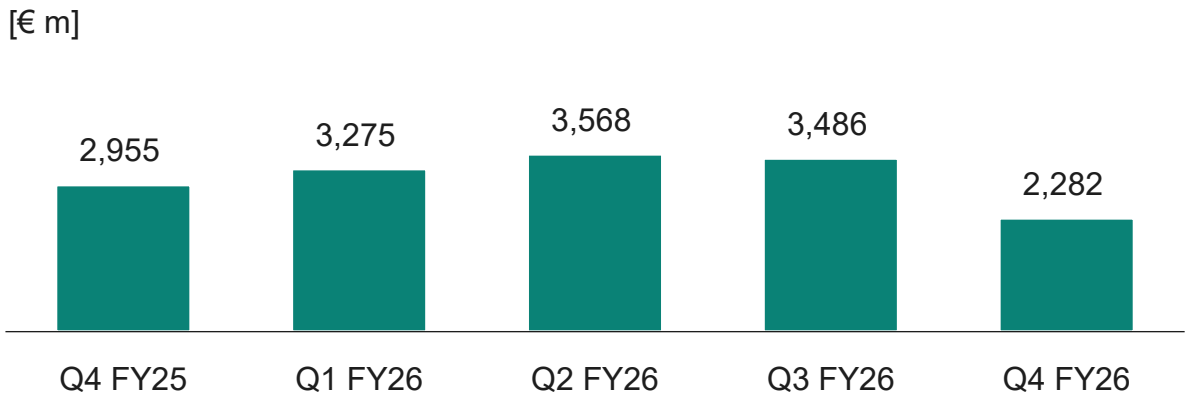


*FCF incl. 2,180m acquisition related outflows for Marvell's automotive Ethernet business

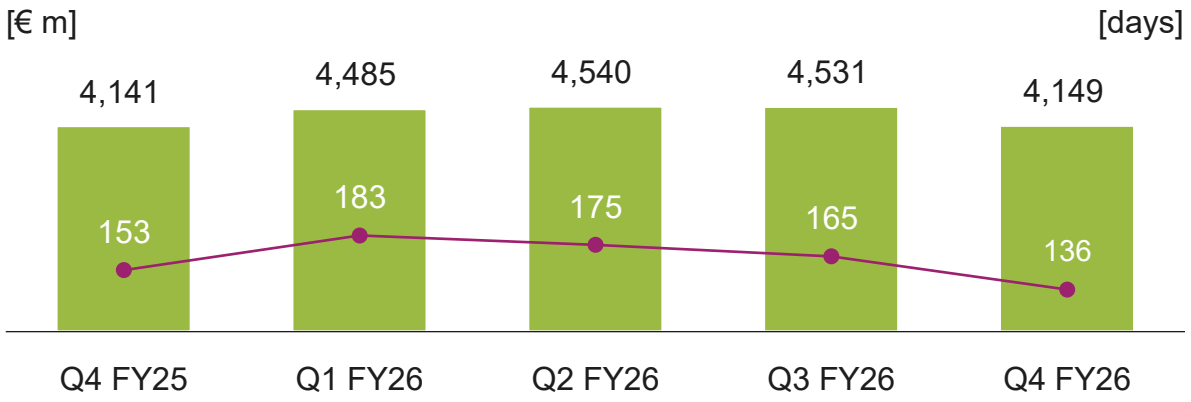
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Working capital, in particular trade working capital components

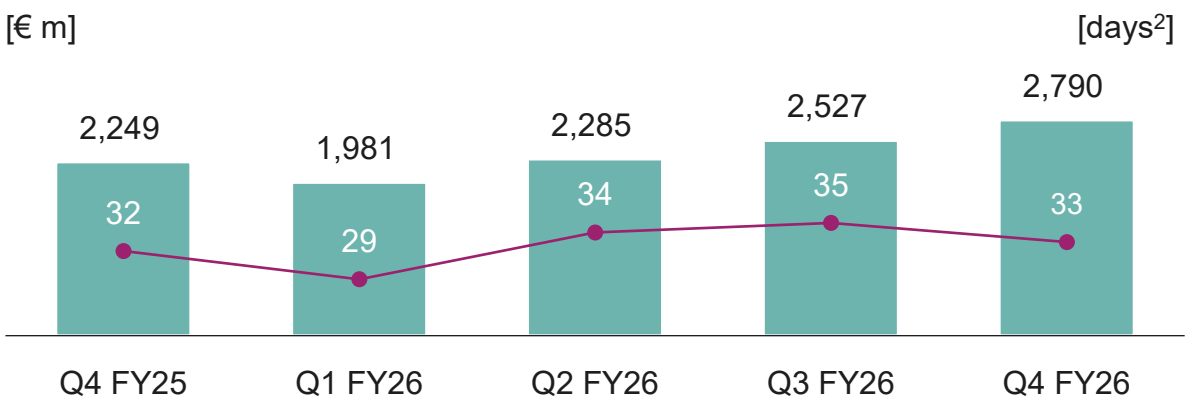
Working capital[1]



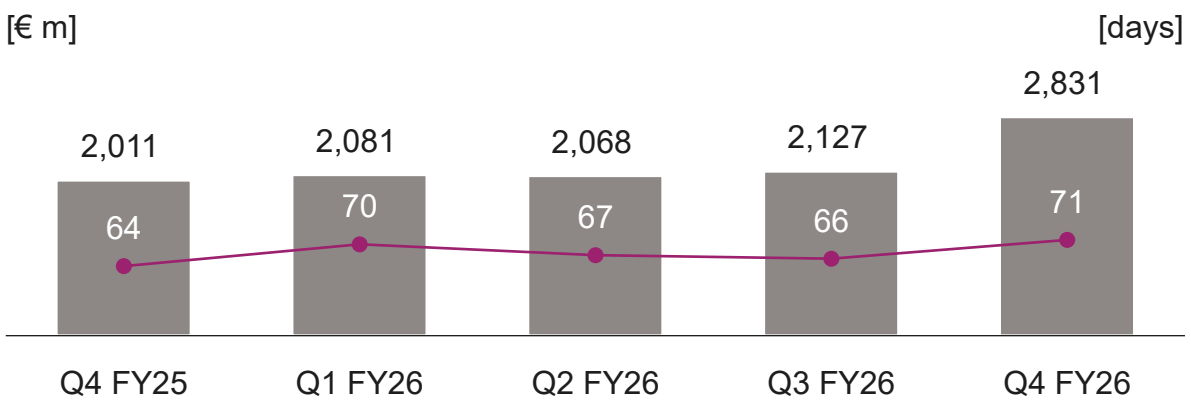
Inventories



Trade receivables



Trade payables

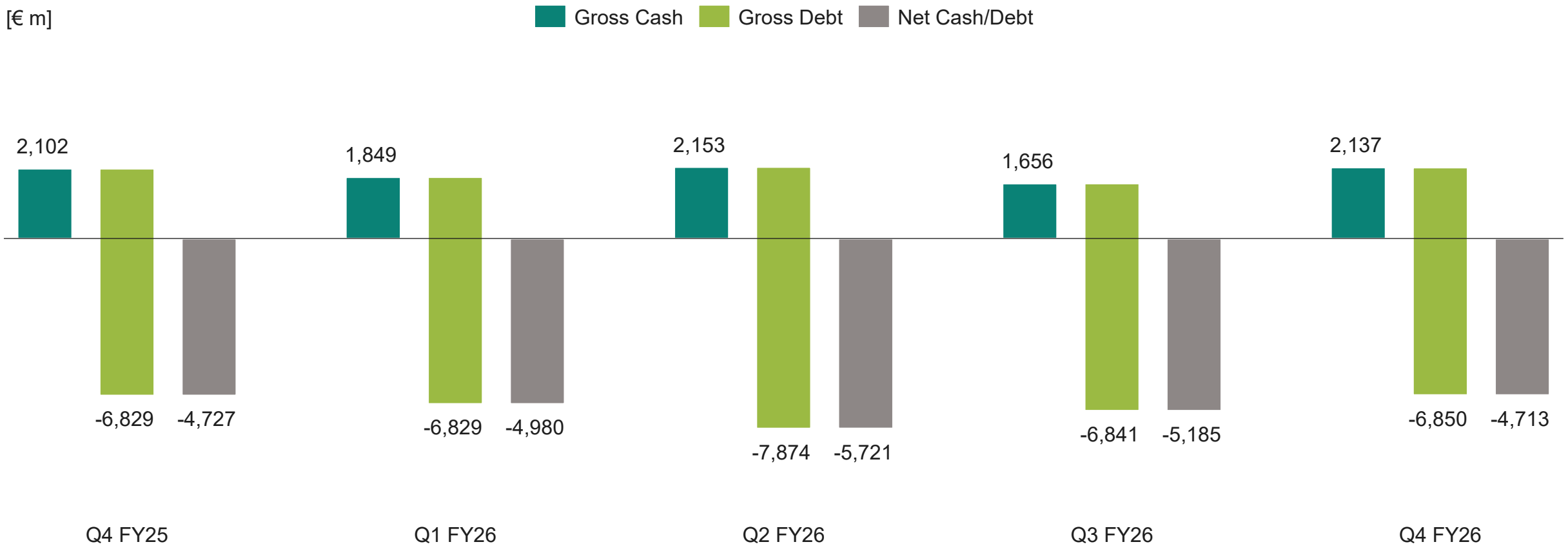


[1] See notes for definition
[2] The calculation of DSO was adjusted effective 1 October 2025. The adjustment increases the transparency and informative value of the key figure and improves its comparability. The figures for the comparative periods have been adjusted accordingly.

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Development of liquidity and debt

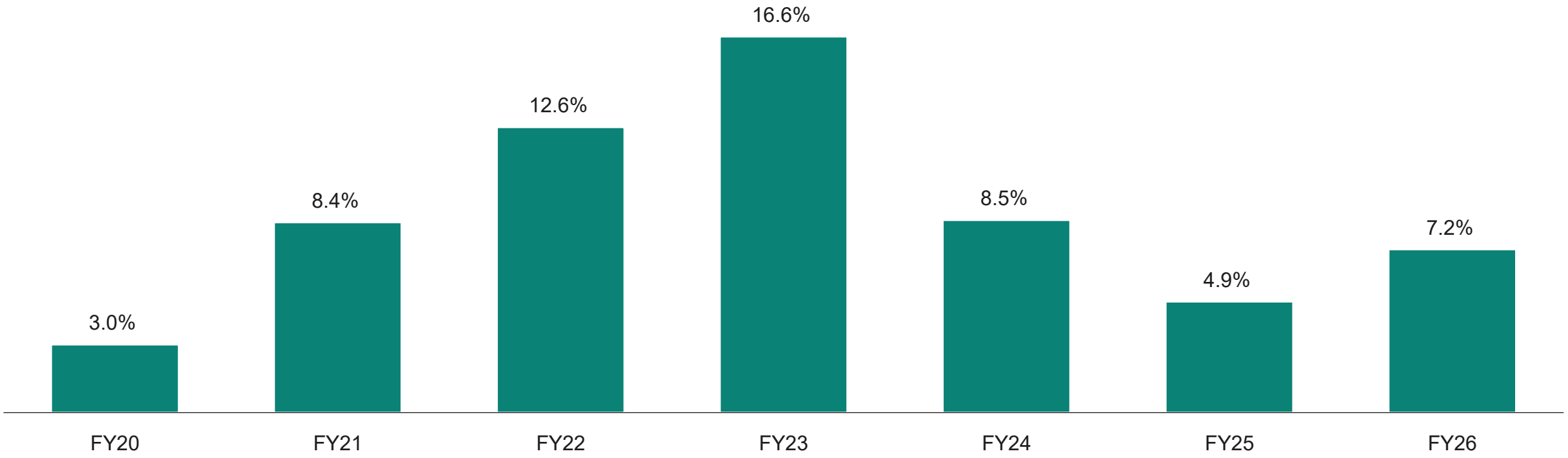
Capital structure



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Return on capital employed

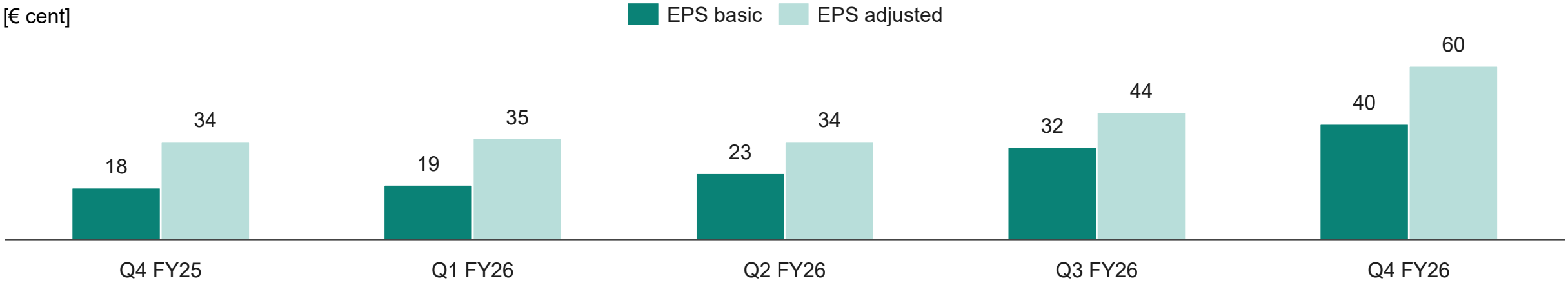
Historical development



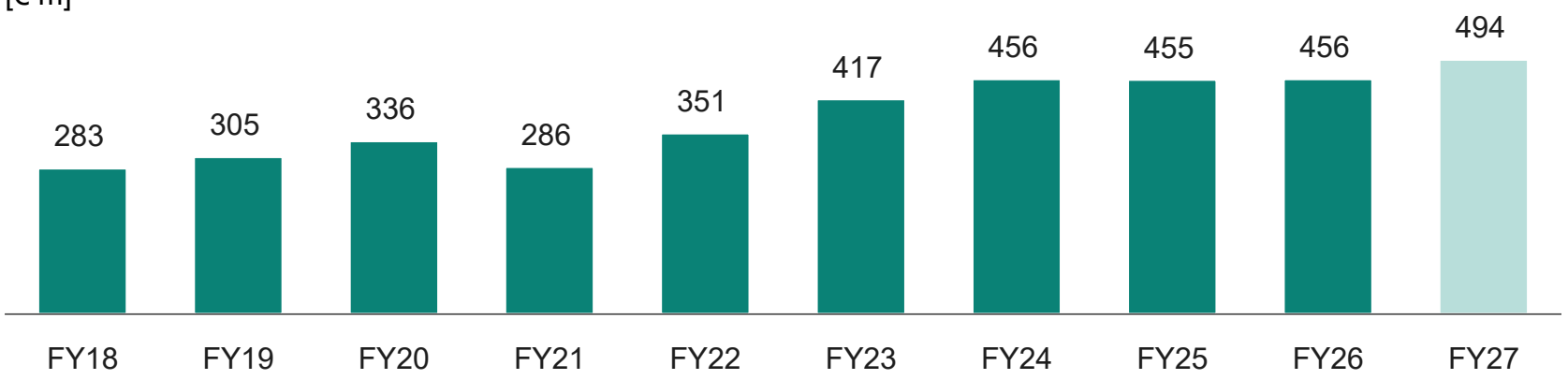
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Earnings-per-share and total cash return

Development of earnings-per-share (EPS) from continuing operations



Total cash return to shareholders via dividends

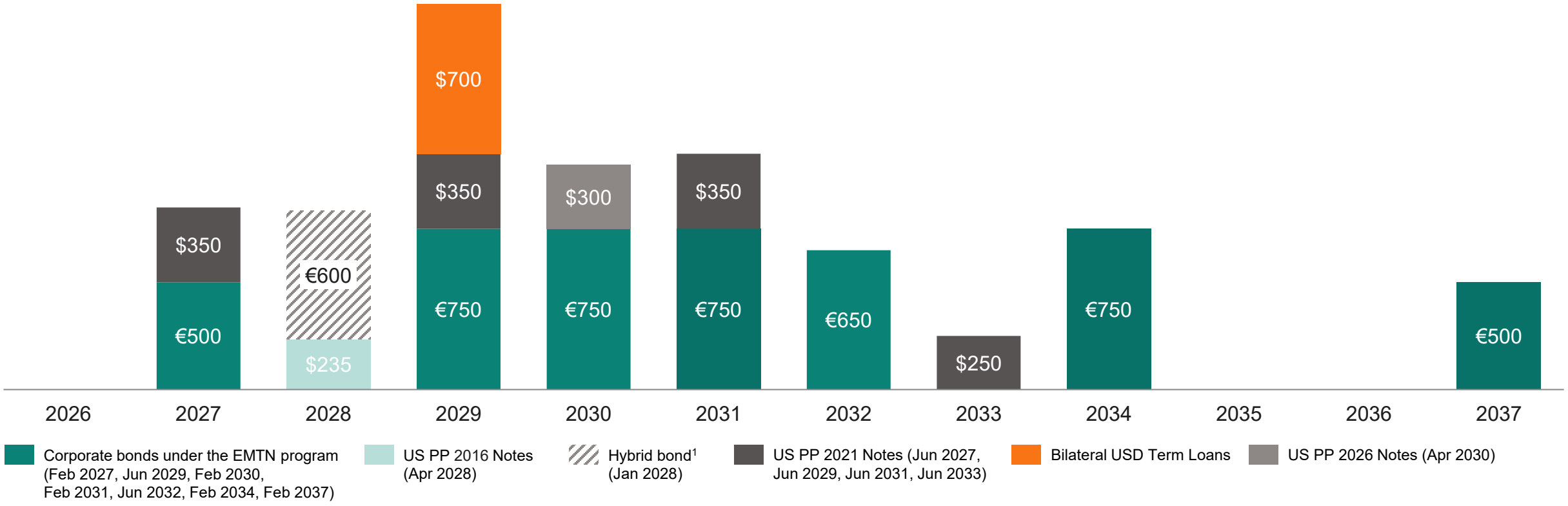


- Dividend for FY26: €0.38 per share
- Payout proposal of €494m

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Maturity profile for calendar years 2026 to 2037

[EUR m; USD m; nominal values]



1 On 1 Oct 2019, Infineon issued a €600m perpetual hybrid bond with first call date in 2028; the hybrid bond is accounted as equity under IFRS.

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Conservative financial policy and strict commitment to investment-grade rating are the basis for through-cycle flexibility

	Financial Policy Targets	Status Quo (LTM 30 September 2026)
Gross Cash[1]	At least **10%** of revenue on average	**~13%** of revenue (€2.1bn)
Gross Debt[2]	**≤ 2.0x** EBITDA	**1.7x** EBITDA
Comfortable liquidity position	– Flexibility for financing operating activities and investments through the cycle	
Balanced debt position	– Gross debt target commensurate with investment-grade rating	
Rating	Investment grade	**BBB+** stable outlook (by S&P Global Ratings)[3]

[1] Gross cash position is defined as cash and cash equivalents plus financial investments | [2] Gross debt is defined as short-term debt and current maturities of long-term debt plus long-term debt. EBITDA is calculated as the total of earnings from continued operations before interest and taxes plus scheduled depreciation and amortization | [3] Latest confirmation February 2026

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New divisional structure

FY26 revenue of €16,353m by segment and key application

ATV 51% of FY25 / 48% of FY26

	Q1	Q2	Q3	Q4	FY25	FY26
Revenue	1,833	1,845	1,955	2,131	**7,425**	**7,765**
Segment Result	402	328	353	469	**1.513**	**1.552**
Segment Result Margin	21.9%	17.8%	18.1%	22.0%	**20.4%**	**20.0%**

ES 21% of FY25 / 19% of FY26

	Q1	Q2	Q3	Q4	FY25	FY26
Revenue	748	762	805	838	**3,095**	**3,154**
Segment Result	80	77	114	124	**431**	**395**
Segment Result Margin	10.7%	10.1%	14.2%	14.8%	**13.9%**	**12.5%**

PS 28% of FY25 / 33% of FY26

	Q1	Q2	Q3	Q4	FY25	FY26
Revenue	1,081	1,205	1,411	1,737	**4,139**	**5,434**
Segment Result	179	248	326	523	**624**	**1.277**
Segment Result Margin	16.6%	20.5%	23.1%	30.1%	**15.1%**	**23.5%**

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Old divisional structure

FY26 revenue of €16,353m by segment and key application

ATV 50% of FY25 / 47% of FY26

	Q1	Q2	Q3	Q4	FY25	FY26
Revenue	1,821	1,830	1,932	2,089	**7,402**	**7,672**
Segment Result	403	331	356	468	**1,529**	**1,559**
Segment Result Margin	22.1%	18.1%	18.4%	22.4%	**20.7%**	**20.3%**

GIP 11% of FY25 / 10% of FY26

	Q1	Q2	Q3	Q4	FY25	FY26
Revenue	349	403	447	503	**1,548**	**1,703**
Segment Result	31	47	44	69	**210**	**191**
Segment Result Margin	8.9%	11.7%	9.8%	13.7%	**13.6%**	**11.2%**

PSS 29% of FY25 / 35% of FY26

	Q1	Q2	Q3	Q4	FY25	FY26
Revenue	1,171	1,260	1,442	1,796	**4,291**	**5,670**
Segment Result	204	257	359	554	**674**	**1,374**
Segment Result Margin	17.4%	20.4%	24.9%	30.8%	**15.7%**	**24.2%**

CSS 10% of FY25 / 8% of FY26

	Q1	Q2	Q3	Q4	FY25	FY26
Revenue	321	319	350	318	**1,418**	**1,308**
Segment Result	23	18	34	25	**155**	**100**
Segment Result Margin	7.2%	5.6%	9.7%	7.9%	**10.9%**	**7.6%**

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Glossary

AC	alternating current
AD	automated driving
ADAS	advanced driver assistance system
AI	artificial intelligence
BBU	battery back-up unit
BEV	battery electric vehicle
BLE	Bluetooth low energy
BMS	battery management system
BoM	bill of materials
BVM	backside vertical module
DC	direct current
DSC/SSC	double/single sided cooling
E/E	electrical/electronic architecture
ECPD	electronic circuit protection device
ECU	electronic control unit
EMS	electronics manufacturing service
ESS	energy storage system
EV	electric vehicle
FCEV	fuel cell electric vehicle
FHEV/MHEV	full/mild hybrid electric vehicle
GaN	gallium nitride
GPU	graphic processing unit
HEMT	high-electron-mobility transistor
HFT	high-frequency transformation
HV	high voltage
HVAC	heating, ventilation, air conditioning
HVDC	high-voltage direct current
IBC	intermediate bus converter
IC	integrated circuit
ICE	internal combustion engine
IGBT	insulated gate bipolar transistor
IoT	internet of things
LED	light-emitting diode
LLC	resonant tank converter
MCU	microcontroller unit
LV	low voltage
MEMS	micro electro-mechanical system
MOSFET	metal-oxide silicon field-effect transistor
MPU	micro processing unit
MV	medium voltage
NFC	near-field communication
OBC	on-board charger
OEM	original equipment manufacturer
P2S	Infineon's strategic product-to-system approach
PCS	power capacitor system
PFC	power factor correction
PDN	power delivery network
PHEV	plug-in hybrid electric vehicle
PHY	physical layer transceiver
PMIC	power management integrated circuits
PSU	power supply unit
RAM	random access memory
RF	radio frequency
SAE	Society of Automotive Engineers
SAM	serviceable available market
SDK	software development kit
Si	silicon
SiC	silicon carbide
SiVR	substrate integrated voltage regulator
SoC	system-on-chip / state of charge
SSCB	solid-state circuit breaker
SST	solid-state transformer
ToF	time-of-flight
UPS-ESS	uninterruptable power supply energy storage solution
UWB	ultra-wideband
VRM	voltage regulator module
xSC	different switched capacitor topologies

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Notes and ESG footnotes

Investments =	'Investments in property, plant and equipment' + 'Investments in other intangible assets and capitalized developments costs'
Adjusted Free Cash Flow Margin =	Adjusted for large investments in frontend buildings and major M&A transactions, for full definition see chapter "Internal management system" in the annual report
Capital Employed =	'Total assets' – 'Cash and cash equivalents' – 'Financial investments' – 'Assets classified as held for sale' – ('Total Current liabilities' – 'Short-term financial debt and current maturities of long-term financial debt' – 'Liabilities classified as held for sale')
RoCE =	'Operating profit from continuing operations'/'Capital Employed' = 'Profit (loss) from continuing operations adjusted for interest result'/'Capital Employed'
Working Capital =	('Total current assets' – 'Cash and cash equivalents' – 'Financial investments' – 'Assets classified as held for sale') – ('Total current liabilities' – 'Short term financial debt and current portion of long-term financial debt' – 'Liabilities classified as held for sale')
DIO (days inventory outstanding; quarter-to-date) =	('Net Inventories'/'Cost of goods sold') x 90
DPO (days payables outstanding; quarter-to-date) =	('Trade payables'/['Cost of goods sold' + 'Purchase of property, plant and equipment']) x 90
DSO (days sales outstanding; quarter-to-date) =	('Trade receivables' - 'reimbursement obligation' + 'contract assets') / 'revenue' x 90

Order backlog =	The total amount of orders received regardless of their current status

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Financial calendar

Date	Event	Location
17-18 November 2026	JP Morgan APAC Technology, Innovation & Growth Conference	Hongkong
19-20 November 2026	Morgan Stanley TMT Conference	Barcelona
24 November 2026	Barclays Sustainable Future Forum 2026	(virtual)
24-25 November 2026	Goldman Sachs, European AI and Semis Symposium	London
30 November 2026	UBS Tech Conference	Scottsdale
7 December 2026	ATV – Divisional Update Call with Peter Schiefer, Head of ATV	London
8 December 2026	Kepler Cheuvreux One-Stop-Shop Conference	Munich
3 February 2027[1]	Earnings Release for the First Quarter of the 2027 Fiscal Year	
25 February 2027[1]	Annual General Meeting 2027	
5 May 2027[1]	Earnings Release for the Second Quarter of the 2027 Fiscal Year	

[1] Preliminary

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